
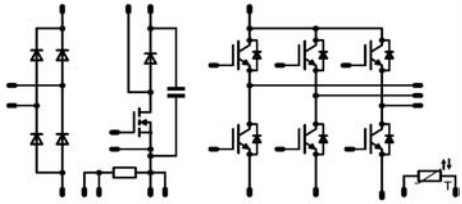


| flowPIM0+PFC 2nd | 600V/20A |
|---|---|
| <div style="border: 1px solid black; padding: 5px; margin-bottom: 5px;"> <p style="text-align: center; background-color: #000080; color: white; margin: 0;">Features</p> <ul style="list-style-type: none"> Clip in PCB mounting Trench Fieldstop IGBT's for low saturation losses Latest generation superjunction MOSFET for PFC </div> <div style="border: 1px solid black; padding: 5px; margin-bottom: 5px;"> <p style="text-align: center; background-color: #000080; color: white; margin: 0;">Target Applications</p> <ul style="list-style-type: none"> Industrial Drives Embedded Drives </div> <div style="border: 1px solid black; padding: 5px;"> <p style="text-align: center; background-color: #000080; color: white; margin: 0;">Types</p> <ul style="list-style-type: none"> 10-F006PPA020SB-M685B </div> | <div style="border: 1px solid black; padding: 5px; margin-bottom: 5px;"> <p style="text-align: center; background-color: #000080; color: white; margin: 0;">flowPIM0+PFC 2nd</p>  </div> <div style="border: 1px solid black; padding: 5px;"> <p style="text-align: center; background-color: #000080; color: white; margin: 0;">Schematic</p>  </div> |

Maximum Ratings

$T_j=25^{\circ}\text{C}$, unless otherwise specified

| Parameter | Symbol | Condition | Value | Unit |
|---------------------------------|------------|--|----------|----------------------|
| Input Rectifier Diode | | | | |
| Repetitive peak reverse voltage | V_{RRM} | | 1600 | V |
| DC forward current | I_{FAV} | $T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$ | 26 36 | A |
| Surge forward current | I_{FSM} | $t_p=10\text{ms}$ $T_j=150^{\circ}\text{C}$ | 200 | A |
| I2t-value | I^2t | | 200 | A^2s |
| Power dissipation per Diode | P_{tot} | $T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$ | 32 48 | W |
| Maximum Junction Temperature | T_{jmax} | | 150 | $^{\circ}\text{C}$ |

Maximum Ratings

 $T_j=25^{\circ}\text{C}$, unless otherwise specified

| Parameter | Symbol | Condition | Value | Unit |
|-----------------------------------|---------------|---|----------|--------------------|
| PFC MOSFET | | | | |
| Drain to source breakdown voltage | V_{DS} | | 600 | V |
| DC drain current | I_D | $T_j=T_{j,max}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$ | 20 24 | A |
| Pulsed drain current | $I_{D,pulse}$ | t_p limited by $T_{j,max}$ | 159 | A |
| Avalanche energy, single pulse | E_{AS} | $I_D=9,3\text{A}$ $V_{DD}=50\text{V}$ $T_j=25^{\circ}\text{C}$ | 1135 | mJ |
| Avalanche energy, repetitive | E_{AR} | $I_D=9,3\text{A}$ $V_{DD}=50\text{V}$ $T_j=25^{\circ}\text{C}$ | 1,72 | mJ |
| Avalanche current, repetitive | I_{AR} | | 9,3 | A |
| MOSFET dv/dt ruggedness | dv/dt | | 50 | V/ns |
| Power dissipation | P_{tot} | $T_j=T_{j,max}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$ | 64 97 | W |
| Gate-source peak voltage | V_{GS} | | ± 20 | V |
| Reverse diode dv/dt | dv/dt | $V_{DS}=0\dots 400\text{V}$, $I_{SD} \leq I_D$ $T_j=25^{\circ}\text{C}$ | 15 | V/ns |
| Maximum Junction Temperature | $T_{j,max}$ | | 150 | $^{\circ}\text{C}$ |

PFC Diode

| | | | | |
|---------------------------------|-------------|---|----------|--------------------|
| Peak Repetitive Reverse Voltage | V_{RRM} | $T_j=25^{\circ}\text{C}$ | 600 | V |
| DC forward current | I_F | $T_j=T_{j,max}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$ | 22 28 | A |
| Repetitive peak forward current | I_{FRM} | 60Hz Single Half-Sine Wave | 300 | A |
| Power dissipation | P_{tot} | $T_j=T_{j,max}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$ | 35 53 | W |
| Maximum Junction Temperature | $T_{j,max}$ | | 150 | $^{\circ}\text{C}$ |

PFC Shunt

| | | | | |
|-----------------------------|-----------|--------------------------|----|---|
| DC forward current | I_F | $T_c=25^{\circ}\text{C}$ | 55 | A |
| Power dissipation per Shunt | P_{tot} | $T_c=25^{\circ}\text{C}$ | 3 | W |

Maximum Ratings

 $T_j=25^{\circ}\text{C}$, unless otherwise specified

| Parameter | Symbol | Condition | Value | Unit |
|--------------------------------------|----------------------|--|----------|--------------------|
| Inverter Transistor | | | | |
| Collector-emitter break down voltage | V_{CE} | | 600 | V |
| DC collector current | I_C | $T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$ | 20 27 | A |
| Pulsed collector current | I_{Cpulse} | t_p limited by T_{jmax} | 60 | A |
| Turn off safe operating area | | $V_{CE} \leq 600\text{V}$, $T_j \leq T_{op max}$ | 60 | A |
| Power dissipation per IGBT | P_{tot} | $T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$ | 41 62 | W |
| Gate-emitter peak voltage | V_{GE} | | ± 20 | V |
| Short circuit ratings | t_{SC} V_{CC} | $T_j \leq 150^{\circ}\text{C}$ $V_{GE}=15\text{V}$ | 6 360 | μs V |
| Maximum Junction Temperature | T_{jmax} | | 175 | $^{\circ}\text{C}$ |

Inverter Diode

| | | | | |
|---------------------------------|------------|--|----------|--------------------|
| Peak Repetitive Reverse Voltage | V_{RRM} | $T_j=25^{\circ}\text{C}$ | 600 | V |
| DC forward current | I_F | $T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$ | 26 34 | A |
| Repetitive peak forward current | I_{FRM} | t_p limited by T_{jmax} | 60 | A |
| Power dissipation per Diode | P_{tot} | $T_j=T_{jmax}$ $T_h=80^{\circ}\text{C}$ $T_c=80^{\circ}\text{C}$ | 40 60 | W |
| Maximum Junction Temperature | T_{jmax} | | 175 | $^{\circ}\text{C}$ |

DC link Capacitor

| | | | | |
|----------------|-----------|--------------------------|-----|---|
| Max.DC voltage | V_{MAX} | $T_c=25^{\circ}\text{C}$ | 500 | V |
|----------------|-----------|--------------------------|-----|---|

Thermal Properties

| | | | | |
|---|-----------|--|----------------------------|--------------------|
| Storage temperature | T_{stg} | | -40...+125 | $^{\circ}\text{C}$ |
| Operation temperature under switching condition | T_{op} | | -40...+($T_{jmax} - 25$) | $^{\circ}\text{C}$ |

Insulation Properties

| | | | | |
|----------------------------|----------|--------------------------|----------|----|
| Insulation voltage | V_{is} | $t=2\text{s}$ DC voltage | 4000 | V |
| Creepage distance | | | min 12,7 | mm |
| Clearance | | | min 12,7 | mm |
| Comparative tracking index | CTI | | >200 | |

Characteristic Values

| Parameter | Symbol | Conditions | | | | | Value | | | Unit |
|---|------------|--|--|----------------------------------|---|-----|--------------|------|--|------------|
| | | $V_{GE}[V]$ or $V_{GS}[V]$ | $V_r[V]$ or $V_{CE}[V]$ or $V_{DS}[V]$ | $I_c[A]$ or $I_F[A]$ or $I_D[A]$ | T_j | Min | Typ | Max | | |
| Input Rectifier Diode | | | | | | | | | | |
| Forward voltage | V_F | | | 25 | $T_j=25^\circ\text{C}$ $T_j=125^\circ\text{C}$ | | 1,20 1,17 | | | V |
| Threshold voltage (for power loss calc. only) | V_{td} | | | 25 | $T_j=25^\circ\text{C}$ $T_j=125^\circ\text{C}$ | | 0,92 0,81 | | | V |
| Slope resistance (for power loss calc. only) | r_t | | | 25 | $T_j=25^\circ\text{C}$ $T_j=125^\circ\text{C}$ | | 11 14 | | | m Ω |
| Reverse current | I_r | | 1600 | | $T_j=25^\circ\text{C}$ $T_j=125^\circ\text{C}$ | | | 0,05 | | mA |
| Thermal resistance chip to heatsink per chip | R_{thJH} | Thermal grease thickness \leq 50um $\lambda = 1 \text{ W/mK}$ | | | | | 2,20 | | | K/W |

PFC MOSFET

| | | | | | | | | | | |
|--|--------------|--|----------|------|---------|---|-----|-----------|-----|------------|
| Static drain to source ON resistance | $R_{DS(on)}$ | | 10 | | 15 | $T_j=25^\circ\text{C}$ $T_j=125^\circ\text{C}$ | | 70 140 | | m Ω |
| Gate threshold voltage | $V_{(GS)th}$ | | | | 0,00172 | $T_j=25^\circ\text{C}$ $T_j=125^\circ\text{C}$ | 2,4 | 3 | 3,6 | V |
| Gate to Source Leakage Current | I_{GSS} | | 20 | 0 | | $T_j=25^\circ\text{C}$ $T_j=125^\circ\text{C}$ | | | 100 | nA |
| Zero Gate Voltage Drain Current | I_{DSS} | | 0 | 600 | | $T_j=25^\circ\text{C}$ $T_j=125^\circ\text{C}$ | | | 5 | nA |
| Turn On Delay Time | $t_{d(ON)}$ | Rgoff=8 Ω Rgon=8 Ω | ± 15 | 400 | 21 | $T_j=25^\circ\text{C}$ | | 27 | | ns |
| Rise Time | t_r | | | | | $T_j=125^\circ\text{C}$ | | 25 | | |
| Turn off delay time | $t_{d(OFF)}$ | | | | | $T_j=25^\circ\text{C}$ | | 16 | | |
| Fall time | t_f | | | | | $T_j=125^\circ\text{C}$ | | 16 | | |
| Turn-on energy loss per pulse | E_{on} | | | | | $T_j=25^\circ\text{C}$ | | 148 | | |
| Turn-off energy loss per pulse | E_{off} | | | | | $T_j=125^\circ\text{C}$ | | 155 | | |
| Total gate charge | Q_{GE} | | | | | $T_j=25^\circ\text{C}$ | | 5 | | |
| Gate to source charge | Q_{GS} | | | | | $T_j=125^\circ\text{C}$ | | 4 | | |
| Gate to drain charge | Q_{GD} | $T_j=25^\circ\text{C}$ | | 0,30 | | | | | | |
| Input capacitance | C_{iss} | | | | | $T_j=125^\circ\text{C}$ | | 170 | | nC |
| Output capacitance | C_{oss} | f=1MHz | 0 | 100 | | $T_j=25^\circ\text{C}$ | | 21 | | nC |
| Gate resistance | r_G | | | | | | | 87 | | nC |
| Thermal resistance chip to heatsink per chip | R_{thJH} | Thermal grease thickness \leq 50um $\lambda = 1 \text{ W/mK}$ | | | | | | 3800 | | pF |
| | | | | | | | | 215 | | pF |
| | | | | | | | | 0,85 | | Ω |
| | | | | | | | | 1,09 | | K/W |

PFC Diode

| | | | | | | | | | | |
|--|----------------------------------|--|----------|-----|----|---|--|--------------|-----|------------------|
| Forward voltage | V_F | | | | 30 | $T_j=25^\circ\text{C}$ $T_j=125^\circ\text{C}$ | | 2,42 1,79 | 2,6 | V |
| Reverse leakage current | I_{rm} | | | 600 | | $T_j=25^\circ\text{C}$ $T_j=125^\circ\text{C}$ | | | 100 | μA |
| Peak recovery current | I_{RRM} | Rgon=8 Ω | ± 15 | 400 | 21 | $T_j=25^\circ\text{C}$ | | 9 | | A |
| Reverse recovery time | t_{rr} | | | | | $T_j=125^\circ\text{C}$ | | 18 | | |
| Reverse recovery charge | Q_{rr} | | | | | $T_j=25^\circ\text{C}$ | | 29 | | |
| Reverse recovered energy | E_{rec} | | | | | $T_j=125^\circ\text{C}$ | | 46 | | |
| Peak rate of fall of recovery current | $di(\text{rec})_{\text{max}}/dt$ | | | | | $T_j=25^\circ\text{C}$ | | 0,14 | | |
| | | | | | | $T_j=125^\circ\text{C}$ | | 0,57 | | |
| Thermal resistance chip to heatsink per chip | R_{thJH} | Thermal grease thickness \leq 50um $\lambda = 1 \text{ W/mK}$ | | | | | | 0,02 0,08 | | mWs |
| | | | | | | | | 1554 1125 | | A/ μs |
| | | | | | | | | 2,02 | | K/W |

PFC Shunt

| | | | | | | | | | | |
|--------------------------|-----------|--|--|--|--|--|--|----|----|------------|
| R1 value | R | | | | | | | 10 | | m Ω |
| Temperature coefficient | t_c | 20 $^\circ\text{C}$ to 60 $^\circ\text{C}$ | | | | | | | 30 | ppm/K |
| Internal heat resistance | R_{thi} | | | | | | | | 10 | K/W |
| Inductance | L | | | | | | | | 3 | nH |

Characteristic Values

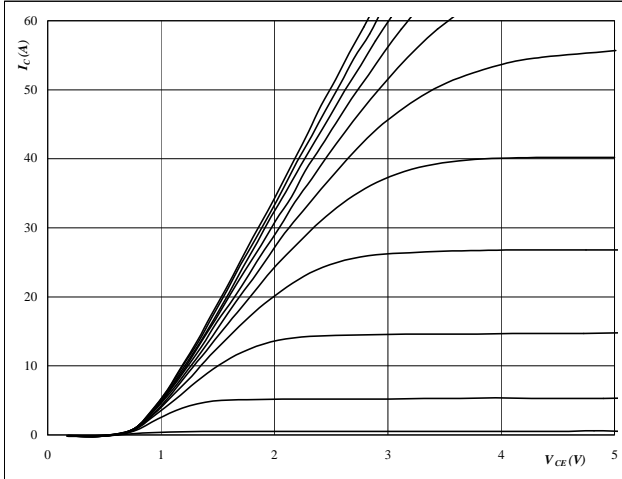
| Parameter | Symbol | Conditions | | | | | Value | | | Unit |
|---|-----------------|---|--|----------------------------------|--------------------|---|-------|--------------|------|----------|
| | | $V_{GE}[V]$ or $V_{GS}[V]$ | $V_r[V]$ or $V_{CE}[V]$ or $V_{DS}[V]$ | $I_c[A]$ or $I_F[A]$ or $I_b[A]$ | T_j | Min | Typ | Max | | |
| Inverter Transistor | | | | | | | | | | |
| Gate emitter threshold voltage | $V_{GE(th)}$ | $V_{CE}=V_{GE}$ | | | 0,00029 | $T_j=25^{\circ}C$ $T_j=125^{\circ}C$ | 5 | 5,6 | 6,5 | V |
| Collector-emitter saturation voltage | $V_{CE(sat)}$ | | 15 | | 20 | $T_j=25^{\circ}C$ $T_j=125^{\circ}C$ | 1,1 | 1,58 1,76 | 1,9 | V |
| Collector-emitter cut-off current incl. Diode | I_{CES} | | 0 | 600 | | $T_j=25^{\circ}C$ $T_j=125^{\circ}C$ | | | 1,1 | μA |
| Gate-emitter leakage current | I_{GES} | | 20 | 0 | | $T_j=25^{\circ}C$ $T_j=125^{\circ}C$ | | | 300 | nA |
| Integrated Gate resistor | R_{gint} | | | | | | | none | | Ω |
| Turn-on delay time | $t_{d(on)}$ | $R_{goff}=16 \Omega$ $R_{gon}=16 \Omega$ | ± 15 | 400 | 20 | $T_j=25^{\circ}C$ | | 67 | ns | |
| Rise time | t_r | | | | | $T_j=125^{\circ}C$ | | 67 | | |
| Turn-off delay time | $t_{d(off)}$ | | | | | $T_j=25^{\circ}C$ | | 27 | | |
| Fall time | t_f | | | | | $T_j=125^{\circ}C$ | | 29 | | |
| Turn-on energy loss per pulse | E_{on} | | | | | $T_j=25^{\circ}C$ | | 126 | | |
| Turn-off energy loss per pulse | E_{off} | $T_j=125^{\circ}C$ | | 145 | $T_j=25^{\circ}C$ | | | 0,68 | mWs | |
| Input capacitance | C_{ies} | | | | $T_j=125^{\circ}C$ | | | 0,96 | | |
| Output capacitance | C_{oss} | $f=1MHz$ | 0 | 25 | | $T_j=25^{\circ}C$ | | 0,48 | pF | |
| Reverse transfer capacitance | C_{rss} | | | | | | | 0,71 | | |
| Gate charge | Q_{Gate} | | ± 15 | 480 | 20 | $T_j=25^{\circ}C$ | | 120 | | nC |
| Thermal resistance chip to heatsink per chip | R_{thJH} | Thermal grease thickness $\leq 50\mu m$ $\lambda = 1 W/mK$ | | | | | | 2,32 | | K/W |
| Inverter Diode | | | | | | | | | | |
| Diode forward voltage | V_F | | | | 30 | $T_j=25^{\circ}C$ $T_j=125^{\circ}C$ | 1,25 | 1,64 1,66 | 1,95 | V |
| Peak reverse recovery current | I_{RRM} | $R_{gon}=16 \Omega$ | ± 15 | 400 | 20 | $T_j=25^{\circ}C$ | | 10 | ns | |
| Reverse recovery time | t_{rr} | | | | | $T_j=125^{\circ}C$ | | 13 | | |
| Reverse recovered charge | Q_{rr} | | | | | $T_j=25^{\circ}C$ | | 204 | | |
| Peak rate of fall of recovery current | $di(rec)max/dt$ | | | | | $T_j=125^{\circ}C$ | | 257 | | |
| Reverse recovered energy | E_{rec} | | | | | $T_j=25^{\circ}C$ | | 1,13 | | |
| Thermal resistance chip to heatsink per chip | R_{thJH} | Thermal grease thickness $\leq 50\mu m$ $\lambda = 1 W/mK$ | | | | | | 0,31 0,54 | | K/W |
| DC link Capacitor | | | | | | | | | | |
| C value | C | | | | | | | 100 | | nF |
| Thermistor | | | | | | | | | | |
| Rated resistance | R | | | | | $T_j=25^{\circ}C$ | | 22000 | | Ω |
| Deviation of R100 | $\dot{O}R/R$ | $R_{100}=1486 \Omega$ | | | | $T_c=100^{\circ}C$ | -5 | | 5 | % |
| Power dissipation | P | | | | | $T_c=100^{\circ}C$ | | 210 | | mW |
| Power dissipation constant | | | | | | $T_j=25^{\circ}C$ | | 3,5 | | mW/K |
| B-value | $B_{(25/50)}$ | Tol. $\pm 3\%$ | | | | $T_j=25^{\circ}C$ | | | | K |
| B-value | $B_{(25/100)}$ | Tol. $\pm 3\%$ | | | | $T_j=25^{\circ}C$ | | 4000 | | K |
| Vincotech NTC Reference | | | | | | $T_j=25^{\circ}C$ | | | A | |

Output Inverter

Figure 1 Output inverter IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

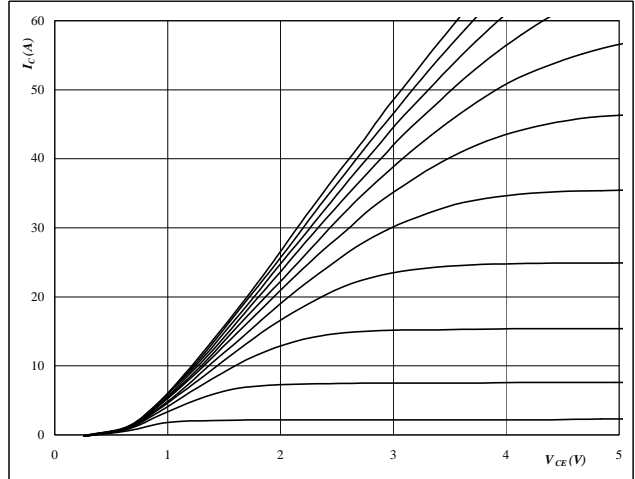


At
 $t_p = 250 \mu s$
 $T_j = 25 \text{ }^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

Figure 2 Output inverter IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

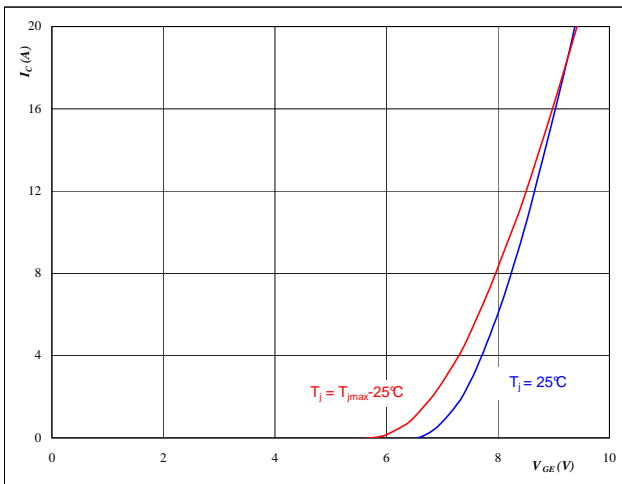


At
 $t_p = 250 \mu s$
 $T_j = 125 \text{ }^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

Figure 3 Output inverter IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$

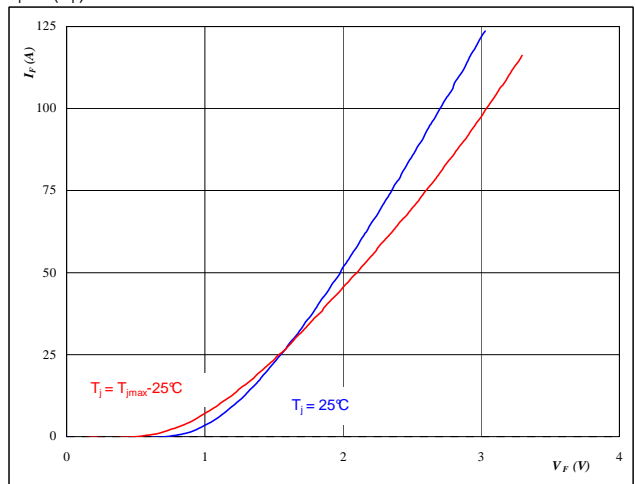


At
 $t_p = 250 \mu s$
 $V_{CE} = 10 V$

Figure 4 Output inverter FWD

Typical diode forward current as a function of forward voltage

$$I_F = f(V_F)$$



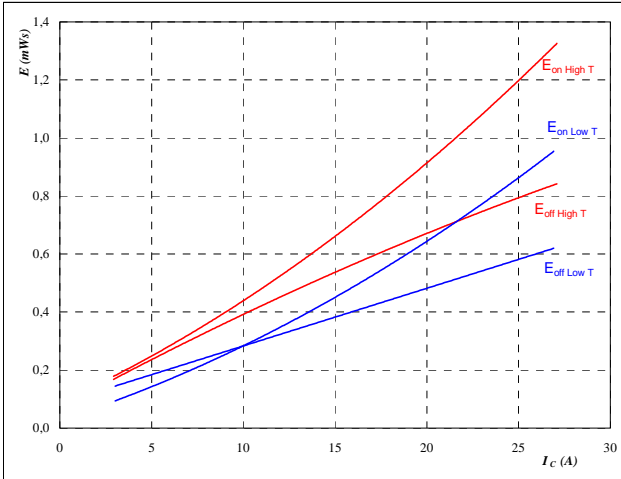
At
 $t_p = 250 \mu s$

Output Inverter

Figure 5 Output inverter IGBT

Typical switching energy losses as a function of collector current

$$E = f(I_C)$$



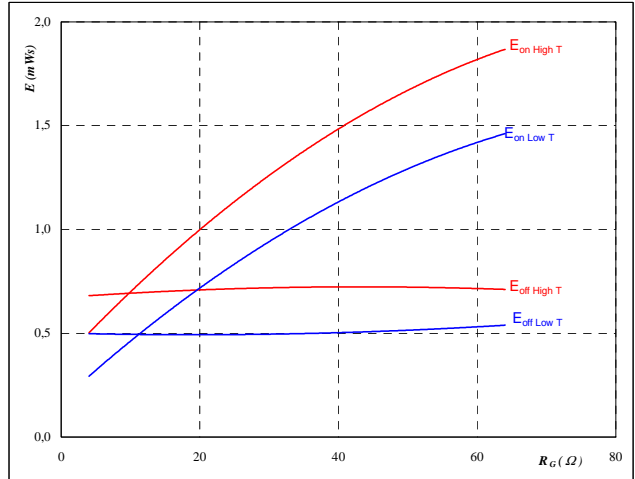
With an inductive load at

| | | |
|--------------|--------|----|
| $T_J =$ | 25/125 | °C |
| $V_{CE} =$ | 400 | V |
| $V_{GE} =$ | ±15 | V |
| $R_{gon} =$ | 16 | Ω |
| $R_{goff} =$ | 16 | Ω |

Figure 6 Output inverter IGBT

Typical switching energy losses as a function of gate resistor

$$E = f(R_G)$$



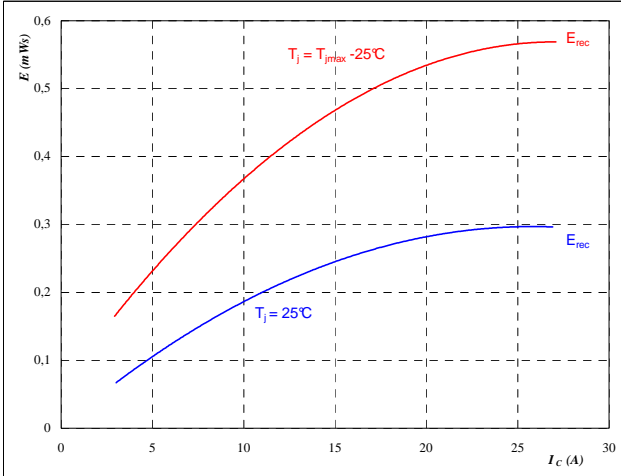
With an inductive load at

| | | |
|------------|--------|----|
| $T_J =$ | 25/125 | °C |
| $V_{CE} =$ | 400 | V |
| $V_{GE} =$ | ±15 | V |
| $I_C =$ | 20 | A |

Figure 7 Output inverter FWD

Typical reverse recovery energy loss as a function of collector current

$$E_{rec} = f(I_C)$$



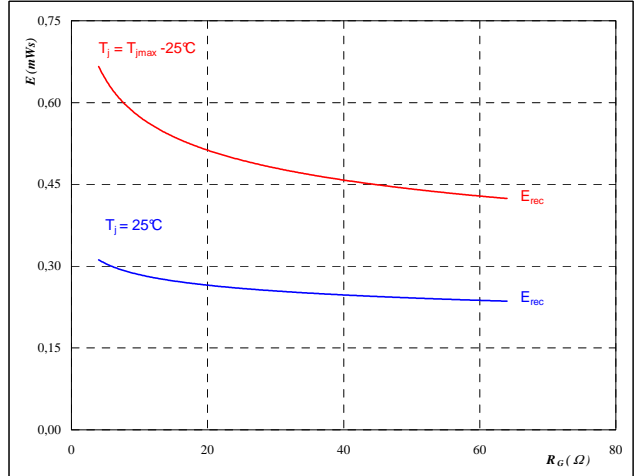
With an inductive load at

| | | |
|-------------|--------|----|
| $T_J =$ | 25/125 | °C |
| $V_{CE} =$ | 400 | V |
| $V_{GE} =$ | ±15 | V |
| $R_{gon} =$ | 16 | Ω |

Figure 8 Output inverter FWD

Typical reverse recovery energy loss as a function of gate resistor

$$E_{rec} = f(R_G)$$



With an inductive load at

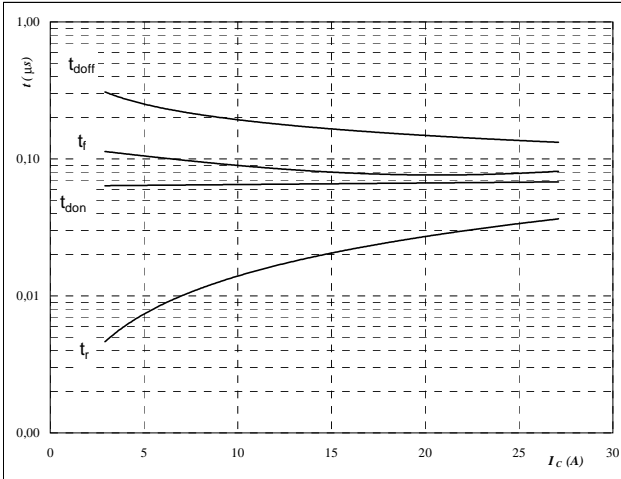
| | | |
|------------|--------|----|
| $T_J =$ | 25/125 | °C |
| $V_{CE} =$ | 400 | V |
| $V_{GE} =$ | ±15 | V |
| $I_C =$ | 20 | A |

Output Inverter

Figure 9 Output inverter IGBT

Typical switching times as a function of collector current

$$t = f(I_C)$$



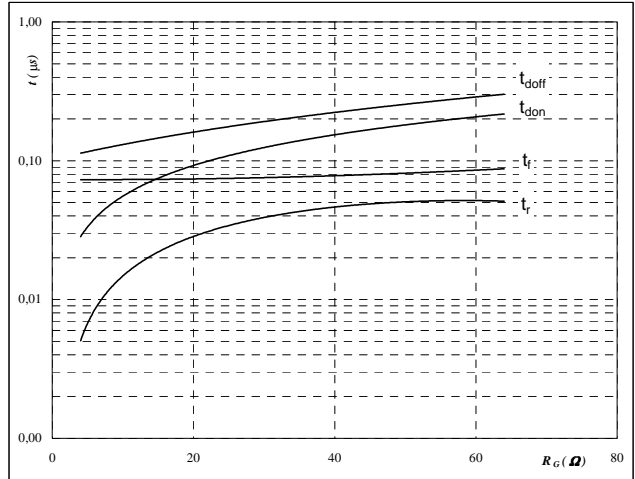
With an inductive load at

| | | |
|---------------------|----------|--------------------|
| $T_j =$ | 125 | $^{\circ}\text{C}$ |
| $V_{\text{CE}} =$ | 400 | V |
| $V_{\text{GE}} =$ | ± 15 | V |
| $R_{\text{gon}} =$ | 16 | Ω |
| $R_{\text{goff}} =$ | 16 | Ω |

Figure 10 Output inverter IGBT

Typical switching times as a function of gate resistor

$$t = f(R_G)$$



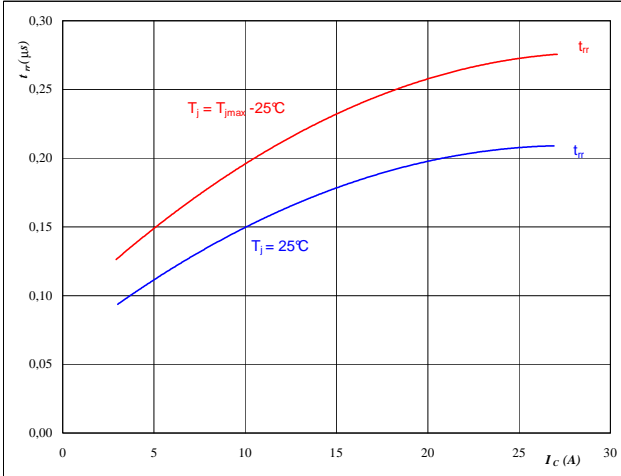
With an inductive load at

| | | |
|-------------------|----------|--------------------|
| $T_j =$ | 125 | $^{\circ}\text{C}$ |
| $V_{\text{CE}} =$ | 400 | V |
| $V_{\text{GE}} =$ | ± 15 | V |
| $I_C =$ | 20 | A |

Figure 11 Output inverter FWD

Typical reverse recovery time as a function of collector current

$$t_{\text{rr}} = f(I_C)$$

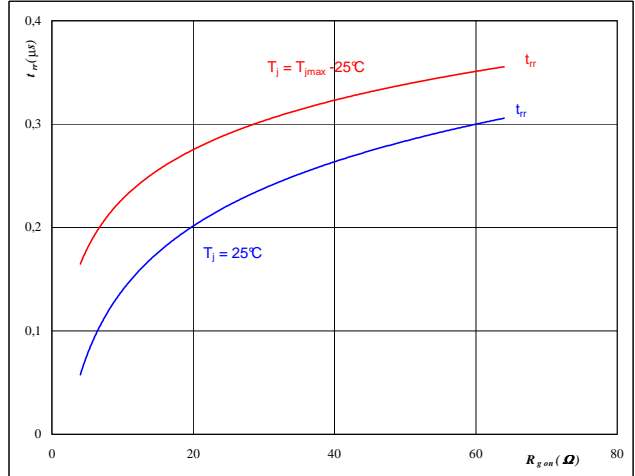

At

| | | |
|--------------------|----------|--------------------|
| $T_j =$ | 25/125 | $^{\circ}\text{C}$ |
| $V_{\text{CE}} =$ | 400 | V |
| $V_{\text{GE}} =$ | ± 15 | V |
| $R_{\text{gon}} =$ | 16 | Ω |

Figure 12 Output inverter FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

$$t_{\text{rr}} = f(R_{\text{gon}})$$


At

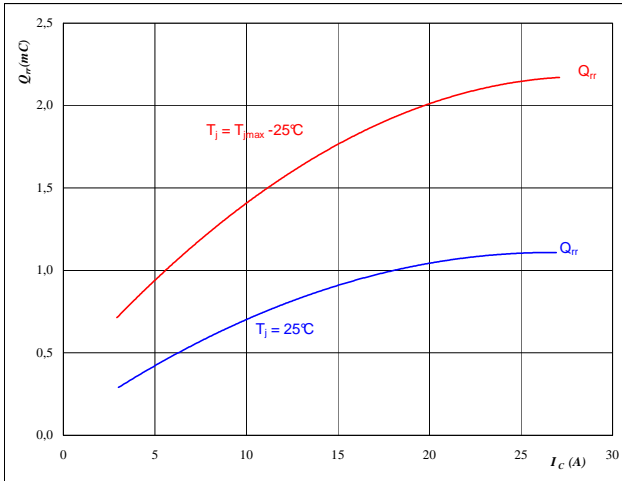
| | | |
|-------------------|----------|--------------------|
| $T_j =$ | 25/125 | $^{\circ}\text{C}$ |
| $V_R =$ | 400 | V |
| $I_F =$ | 20 | A |
| $V_{\text{GE}} =$ | ± 15 | V |

Output Inverter

Figure 13 Output inverter FWD

Typical reverse recovery charge as a function of collector current

$$Q_{rr} = f(I_C)$$



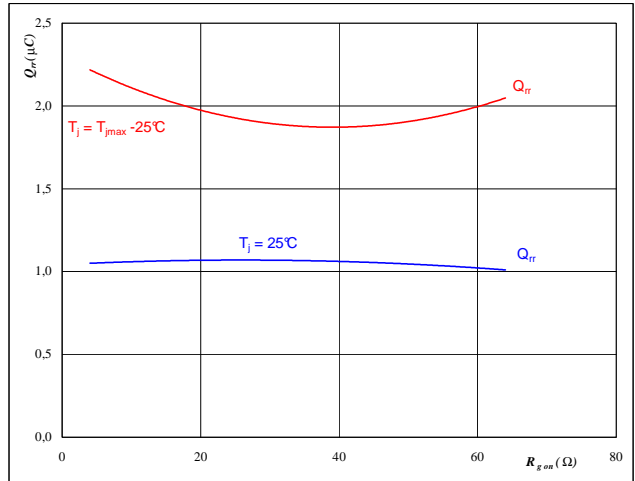
At

| | | |
|-------------|--------|----|
| $T_j =$ | 25/125 | °C |
| $V_{CE} =$ | 400 | V |
| $V_{GE} =$ | ±15 | V |
| $R_{gon} =$ | 16 | Ω |

Figure 14 Output inverter FWD

Typical reverse recovery charge as a function of IGBT turn on gate resistor

$$Q_{rr} = f(R_{gon})$$



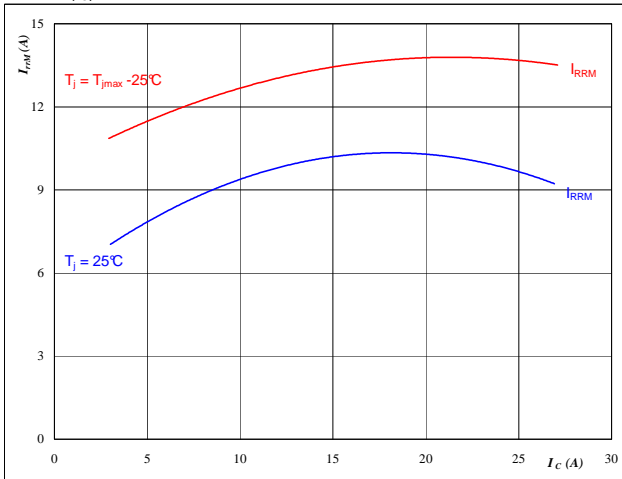
At

| | | |
|------------|--------|----|
| $T_j =$ | 25/125 | °C |
| $V_R =$ | 400 | V |
| $I_F =$ | 20 | A |
| $V_{GE} =$ | ±15 | V |

Figure 15 Output inverter FWD

Typical reverse recovery current as a function of collector current

$$I_{RRM} = f(I_C)$$



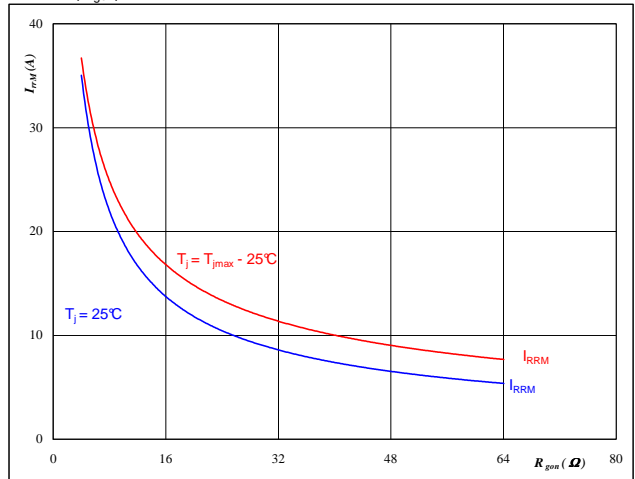
At

| | | |
|-------------|--------|----|
| $T_j =$ | 25/125 | °C |
| $V_{CE} =$ | 400 | V |
| $V_{GE} =$ | ±15 | V |
| $R_{gon} =$ | 16 | Ω |

Figure 16 Output inverter FWD

Typical reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RRM} = f(R_{gon})$$



At

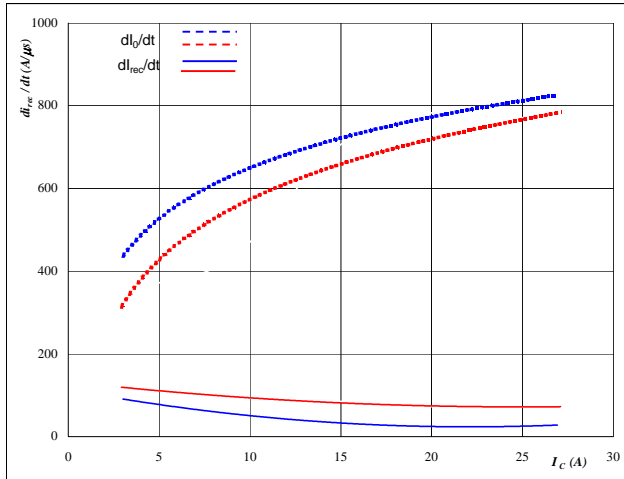
| | | |
|------------|--------|----|
| $T_j =$ | 25/125 | °C |
| $V_R =$ | 400 | V |
| $I_F =$ | 20 | A |
| $V_{GE} =$ | ±15 | V |

Output Inverter

Figure 17 Output inverter FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current

$$di_o/dt, di_{rec}/dt = f(I_C)$$

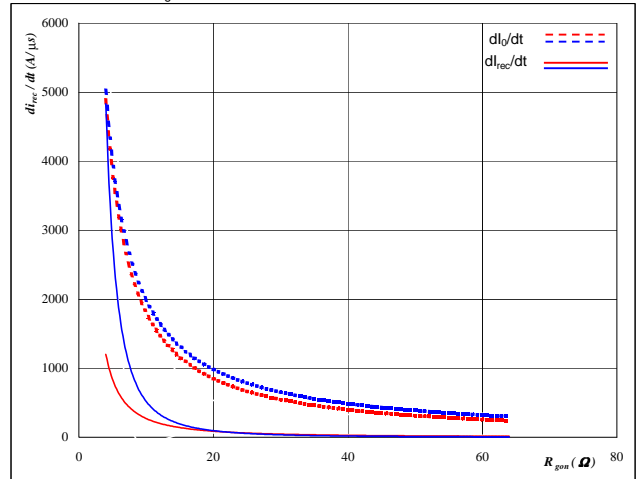


At
 $T_j = 25/125$ °C
 $V_{CE} = 400$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 16$ Ω

Figure 18 Output inverter FWD

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$$di_o/dt, di_{rec}/dt = f(R_{gon})$$

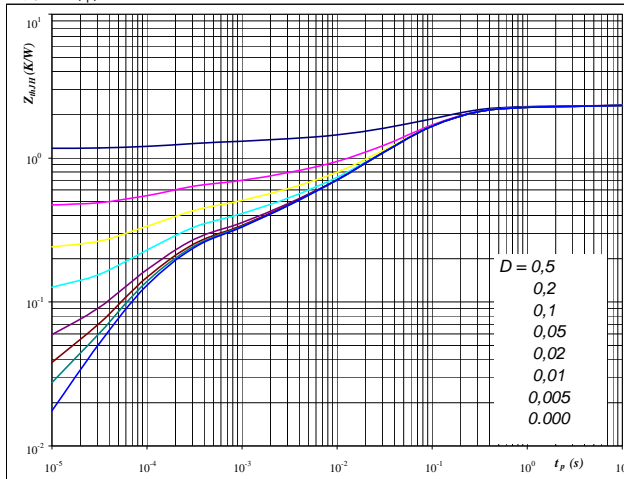


At
 $T_j = 25/125$ °C
 $V_R = 400$ V
 $I_F = 20$ A
 $V_{GE} = \pm 15$ V

Figure 19 Output inverter IGBT

IGBT transient thermal impedance as a function of pulse width

$$Z_{thJH} = f(t_p)$$



At
 $D = t_p / T$
 $R_{thJH} = 2,32$ K/W $R_{thJH} = 1,88$ K/W

IGBT thermal model values

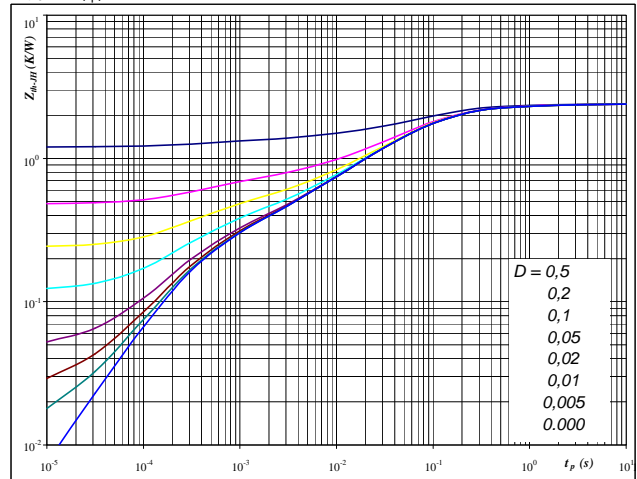
Thermal grease

| R (C/W) | Tau (s) | R (C/W) | Tau (s) |
|---------|---------|---------|---------|
| 0,07 | 4,4E+00 | 0,06 | 3,6E+00 |
| 0,30 | 3,8E-01 | 0,24 | 3,1E-01 |
| 1,26 | 8,1E-02 | 1,02 | 6,6E-02 |
| 0,34 | 1,2E-02 | 0,27 | 9,6E-03 |
| 0,14 | 1,4E-03 | 0,12 | 1,1E-03 |
| 0,21 | 1,3E-04 | 0,17 | 1,0E-04 |

Figure 20 Output inverter FWD

FWD transient thermal impedance as a function of pulse width

$$Z_{thJH} = f(t_p)$$



At
 $D = t_p / T$
 $R_{thJH} = 2,40$ K/W $R_{thJH} = 1,94$ K/W

FWD thermal model values

Thermal grease

| R (C/W) | Tau (s) |
|---------|---------|
| 0,07 | 4,6E+00 |
| 0,27 | 4,8E-01 |
| 1,13 | 8,5E-02 |
| 0,52 | 2,0E-02 |
| 0,20 | 2,8E-03 |
| 0,21 | 3,3E-04 |

Phase change interface

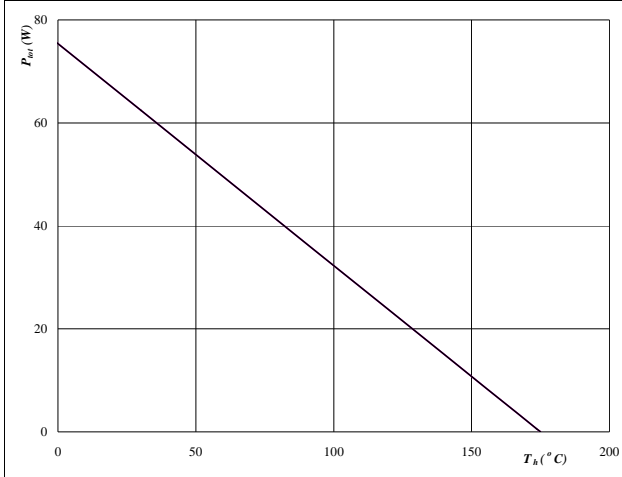
| R (C/W) | Tau (s) |
|---------|---------|
| 0,06 | 3,7E+00 |
| 0,22 | 3,9E-01 |
| 0,92 | 6,9E-02 |
| 0,42 | 1,6E-02 |
| 0,16 | 2,3E-03 |
| 0,17 | 2,7E-04 |

Output Inverter

Figure 21 Output inverter IGBT

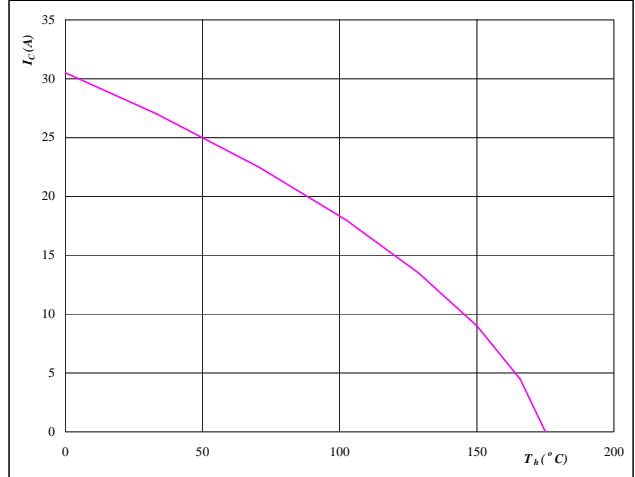
Power dissipation as a function of heatsink temperature

$$P_{tot} = f(T_h)$$


At
 $T_j = 175 \text{ } ^\circ\text{C}$
Figure 22 Output inverter IGBT

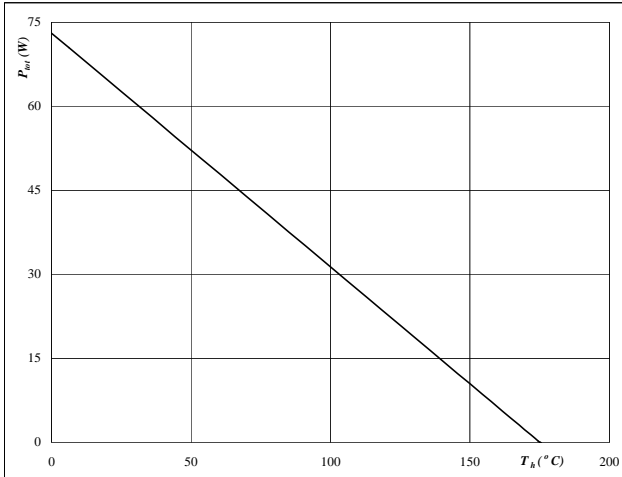
Collector current as a function of heatsink temperature

$$I_C = f(T_h)$$


At
 $T_j = 175 \text{ } ^\circ\text{C}$
 $V_{GE} = 15 \text{ V}$
Figure 23 Output inverter FWD

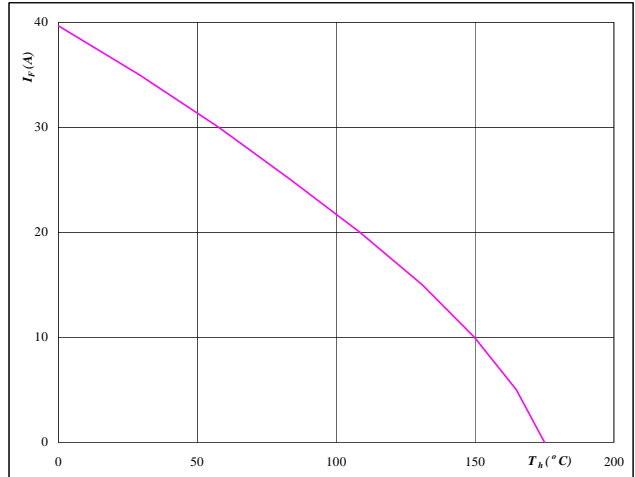
Power dissipation as a function of heatsink temperature

$$P_{tot} = f(T_h)$$


At
 $T_j = 175 \text{ } ^\circ\text{C}$
Figure 24 Output inverter FWD

Forward current as a function of heatsink temperature

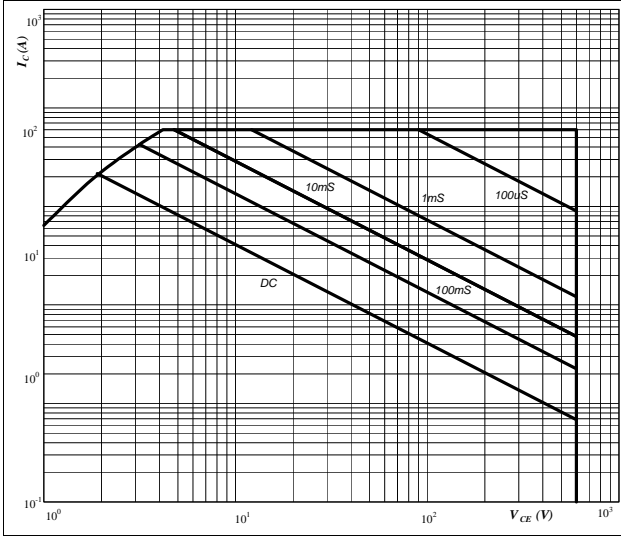
$$I_F = f(T_h)$$


At
 $T_j = 175 \text{ } ^\circ\text{C}$

Output Inverter

Figure 25 Output inverter IGBT

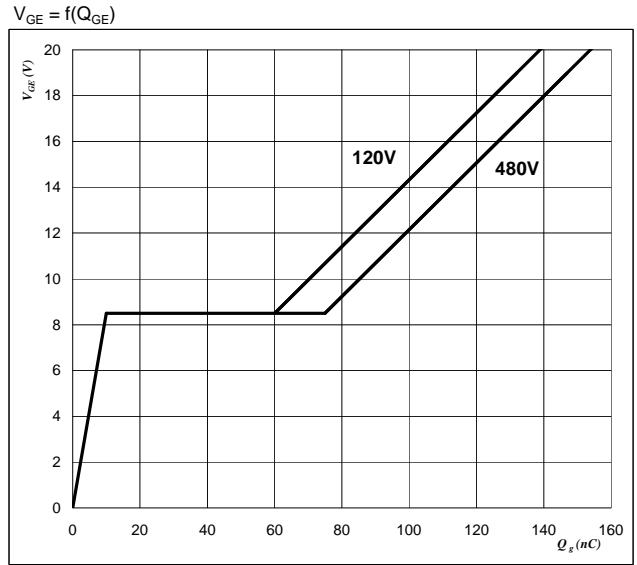
Safe operating area as a function of collector-emitter voltage
 $I_C = f(V_{CE})$



At
 D = single pulse
 $T_h = 80$ °C
 $V_{GE} = \pm 15$ V
 $T_j = T_{jmax}$ °C

Figure 26 Output inverter IGBT

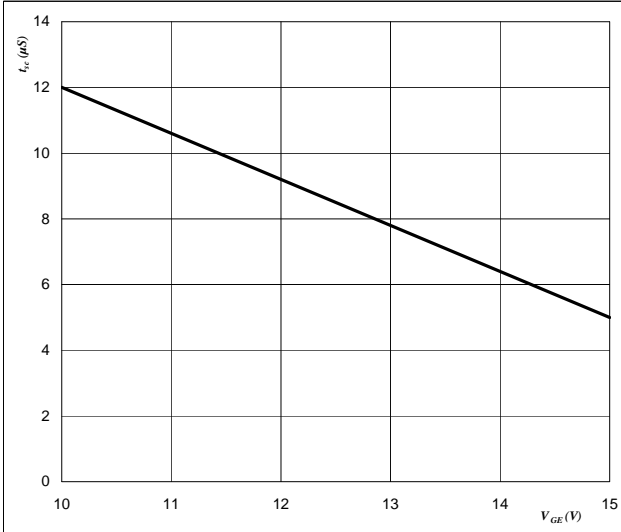
Gate voltage vs Gate charge



At
 $I_C = 20$ A

Figure 27 Output inverter IGBT

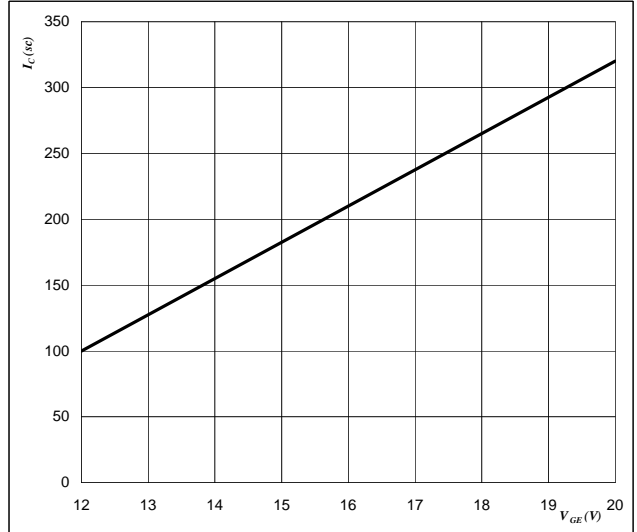
Short circuit withstand time as a function of gate-emitter voltage
 $t_{sc} = f(V_{GE})$



At
 $V_{CE} = 600$ V
 $T_j \leq 175$ °C

Figure 28 Output inverter IGBT

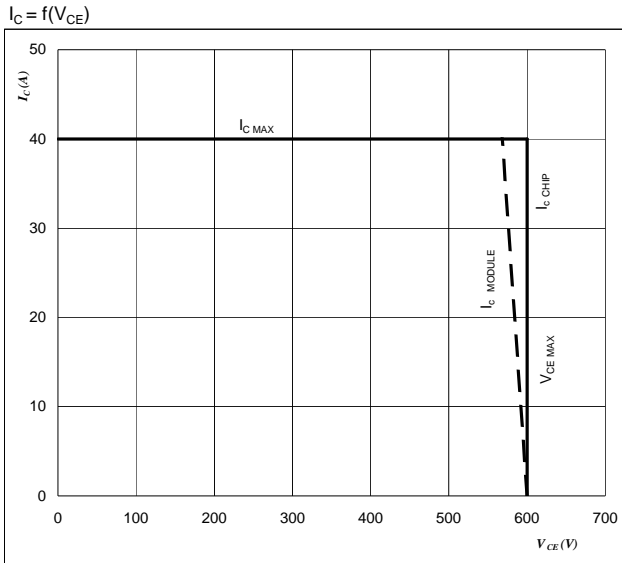
Typical short circuit collector current as a function of gate-emitter voltage
 $V_{GE} = f(Q_{GE})$



At
 $V_{CE} \leq 600$ V
 $T_j = 175$ °C

Output Inverter

Figure 29 IGBT

Reverse bias safe operating area

At

$$T_j = T_{j\ max} - 25 \quad ^\circ\text{C}$$

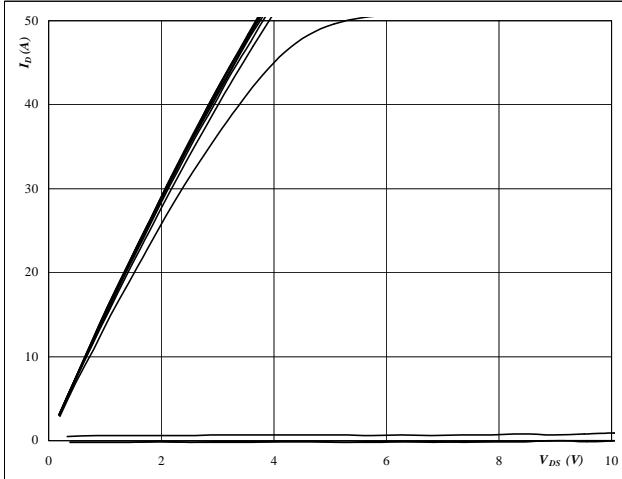
$$U_{cc\ minus} = U_{cc\ plus}$$

Switching mode : 3 level switching

PFC
Figure 1 PFC MOSFET

Typical output characteristics

$I_D = f(V_{DS})$

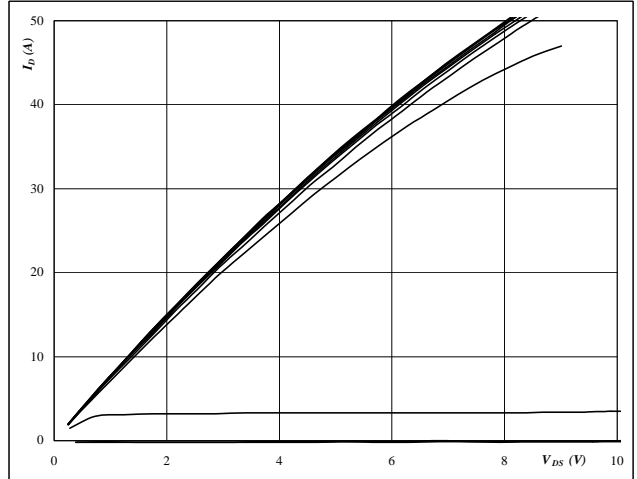


At
 $t_p = 250 \mu s$
 $T_j = 25 \text{ }^\circ C$
 V_{GS} from 0 V to 20 V in steps of 2 V

Figure 2 PFC MOSFET

Typical output characteristics

$I_D = f(V_{DS})$

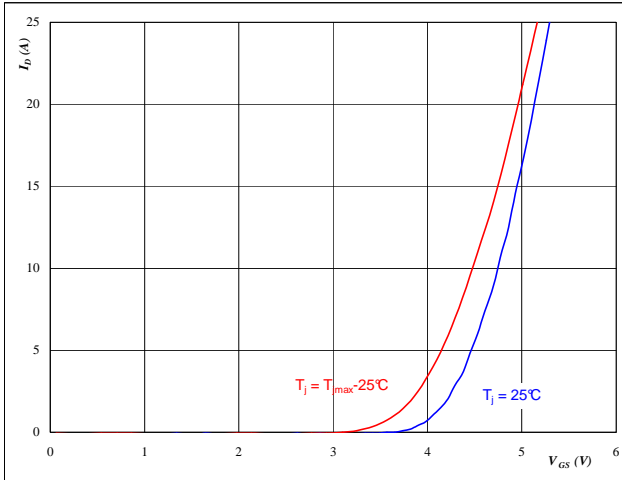


At
 $t_p = 250 \mu s$
 $T_j = 125 \text{ }^\circ C$
 V_{GS} from 0 V to 20 V in steps of 2 V

Figure 3 PFC MOSFET

Typical transfer characteristics

$I_D = f(V_{GS})$

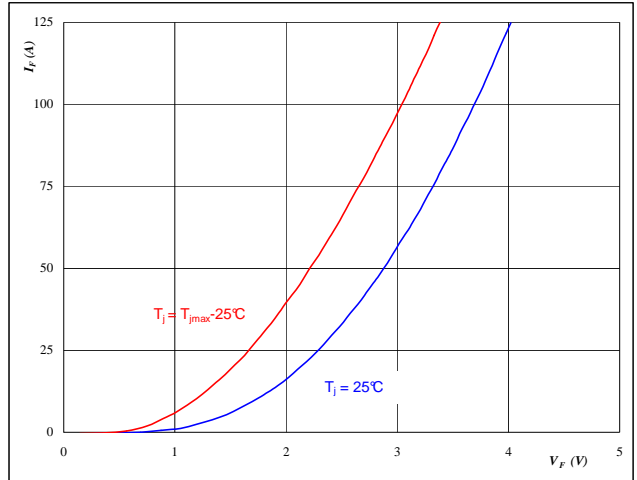


At
 $t_p = 250 \mu s$
 $V_{DS} = 10 V$

Figure 4 PFC FWD

Typical diode forward current as a function of forward voltage

$I_F = f(V_F)$

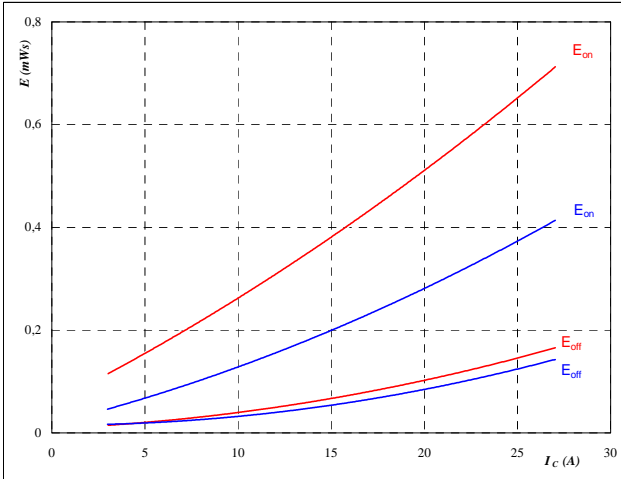


At
 $t_p = 250 \mu s$

PFC
Figure 5 PFC MOSFET

Typical switching energy losses
as a function of collector current

$$E = f(I_D)$$



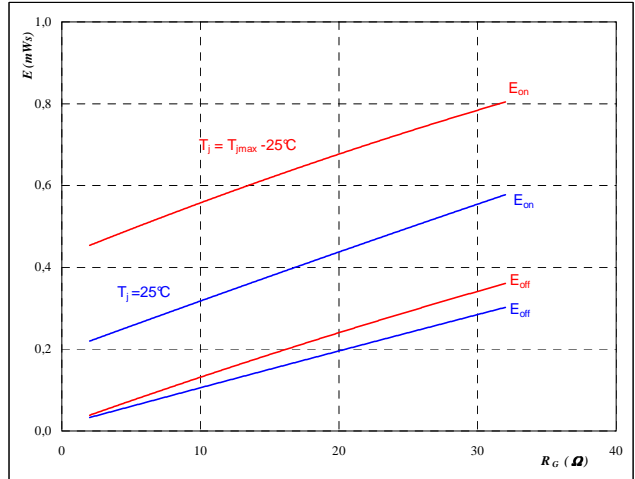
With an inductive load at

| | | |
|--------------|--------|----|
| $T_j =$ | 25/125 | °C |
| $V_{DS} =$ | 400 | V |
| $V_{GS} =$ | 10 | V |
| $R_{gon} =$ | 8 | Ω |
| $R_{goff} =$ | 8 | Ω |

Figure 6 PFC MOSFET

Typical switching energy losses
as a function of gate resistor

$$E = f(R_G)$$



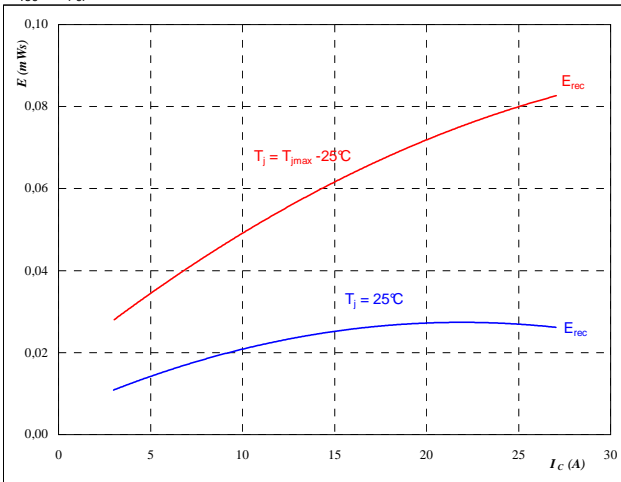
With an inductive load at

| | | |
|------------|--------|----|
| $T_j =$ | 25/125 | °C |
| $V_{DS} =$ | 400 | V |
| $V_{GS} =$ | 10 | V |
| $I_D =$ | 21 | A |

Figure 7 PFC MOSFET

Typical reverse recovery energy loss
as a function of collector (drain) current

$$E_{rec} = f(I_C)$$



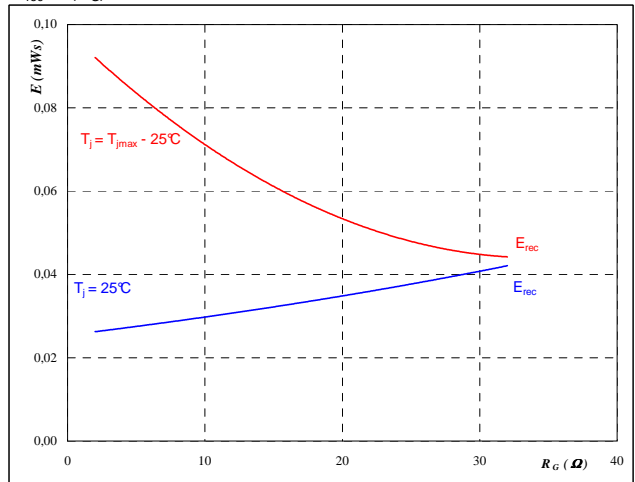
With an inductive load at

| | | |
|--------------|--------|----|
| $T_j =$ | 25/125 | °C |
| $V_{DS} =$ | 400 | V |
| $V_{GS} =$ | 10 | V |
| $R_{gon} =$ | 8 | Ω |
| $R_{goff} =$ | 8 | Ω |

Figure 8 PFC MOSFET

Typical reverse recovery energy loss
as a function of gate resistor

$$E_{rec} = f(R_G)$$



With an inductive load at

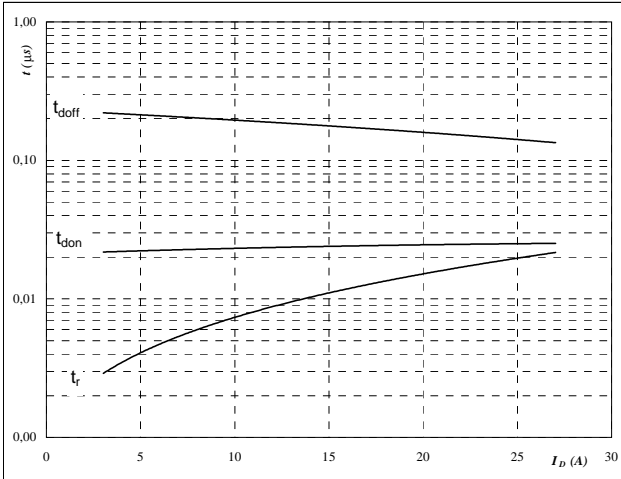
| | | |
|------------|--------|----|
| $T_j =$ | 25/125 | °C |
| $V_{DS} =$ | 400 | V |
| $V_{GS} =$ | 10 | V |
| $I_D =$ | 21 | A |

PFC

Figure 9 PFC MOSFET

Typical switching times as a function of collector current

$t = f(I_C)$



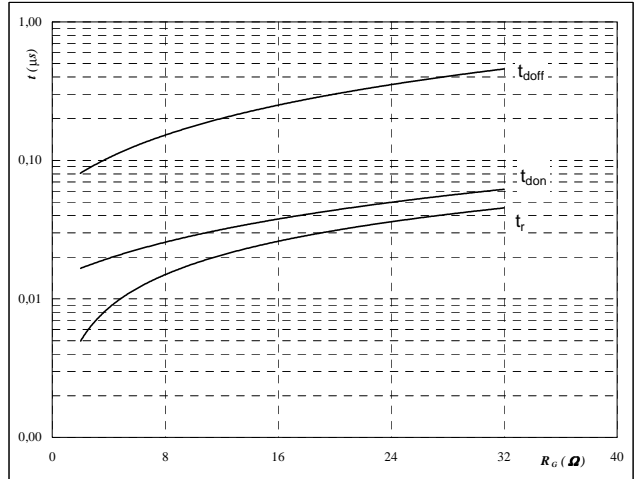
With an inductive load at

| | | |
|--------------|-----|----|
| $T_j =$ | 125 | °C |
| $V_{DS} =$ | 400 | V |
| $V_{GS} =$ | 10 | V |
| $R_{gon} =$ | 8 | Ω |
| $R_{goff} =$ | 8 | Ω |

Figure 10 PFC MOSFET

Typical switching times as a function of gate resistor

$t = f(R_G)$



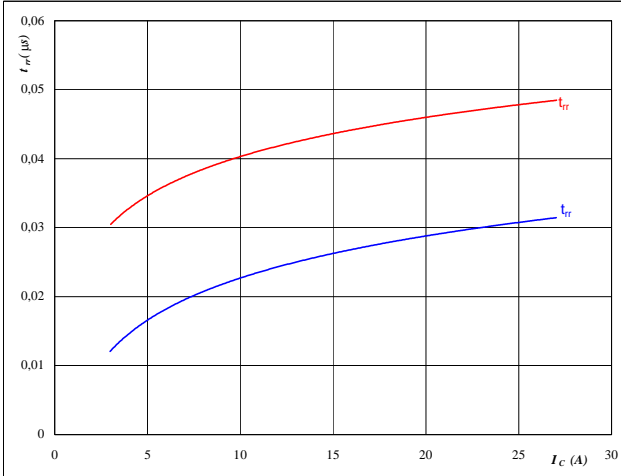
With an inductive load at

| | | |
|------------|-----|----|
| $T_j =$ | 125 | °C |
| $V_{DS} =$ | 400 | V |
| $V_{GS} =$ | 10 | V |
| $I_C =$ | 21 | A |

Figure 11 PFC FWD

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$



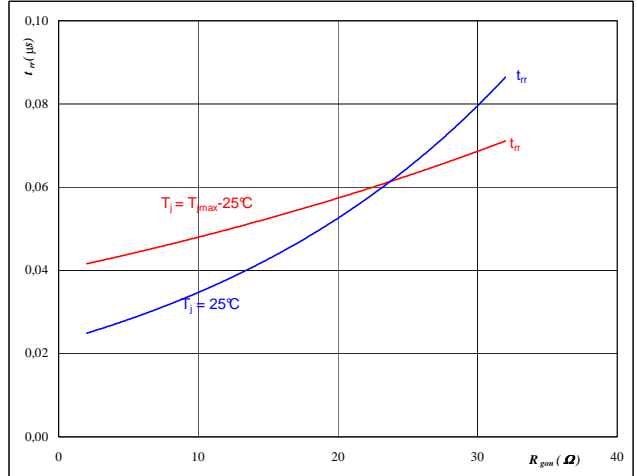
At

| | | |
|-------------|--------|----|
| $T_j =$ | 25/125 | °C |
| $V_{CE} =$ | 400 | V |
| $V_{GE} =$ | 10 | V |
| $R_{gon} =$ | 8 | Ω |

Figure 12 PFC FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



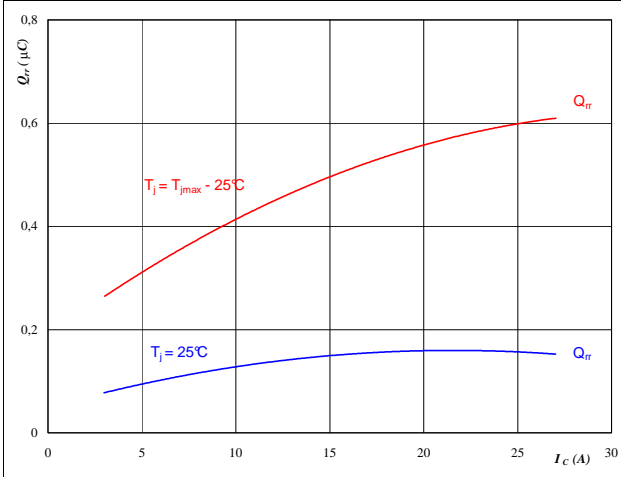
At

| | | |
|------------|--------|----|
| $T_j =$ | 25/125 | °C |
| $V_R =$ | 400 | V |
| $I_F =$ | 21 | A |
| $V_{GS} =$ | 10 | V |

PFC
Figure 13 PFC FWD

Typical reverse recovery charge as a function of collector current

$$Q_{rr} = f(I_C)$$

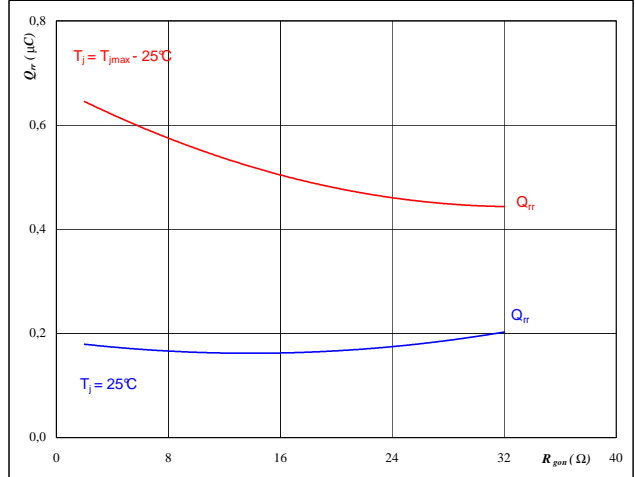

At

| | | |
|-------------|--------|----|
| $T_j =$ | 25/125 | °C |
| $V_{CE} =$ | 400 | V |
| $V_{GE} =$ | 10 | V |
| $R_{gon} =$ | 8 | Ω |

Figure 14 PFC FWD

Typical reverse recovery charge as a function of IGBT turn on gate resistor

$$Q_{rr} = f(R_{gon})$$

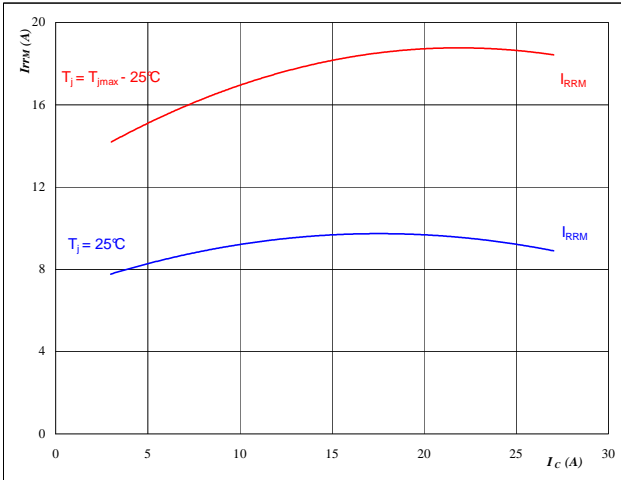

At

| | | |
|------------|--------|----|
| $T_j =$ | 25/125 | °C |
| $V_R =$ | 400 | V |
| $I_F =$ | 21 | A |
| $V_{GS} =$ | 10 | V |

Figure 15 PFC FWD

Typical reverse recovery current as a function of collector current

$$I_{RRM} = f(I_C)$$

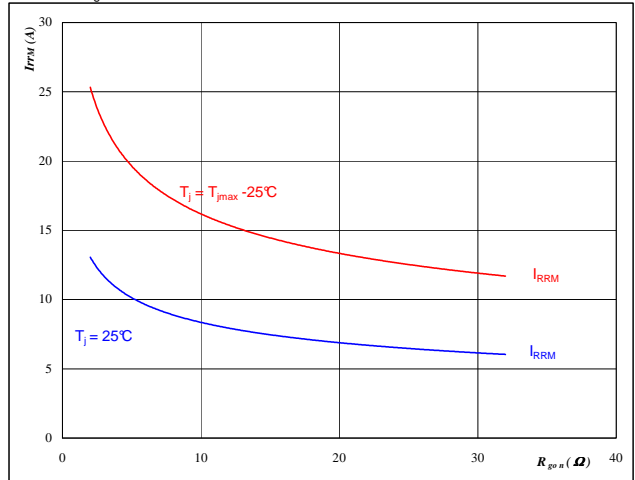

At

| | | |
|-------------|--------|----|
| $T_j =$ | 25/125 | °C |
| $V_{CE} =$ | 400 | V |
| $V_{GE} =$ | 10 | V |
| $R_{gon} =$ | 8 | Ω |

Figure 16 PFC FWD

Typical reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RRM} = f(R_{gon})$$


At

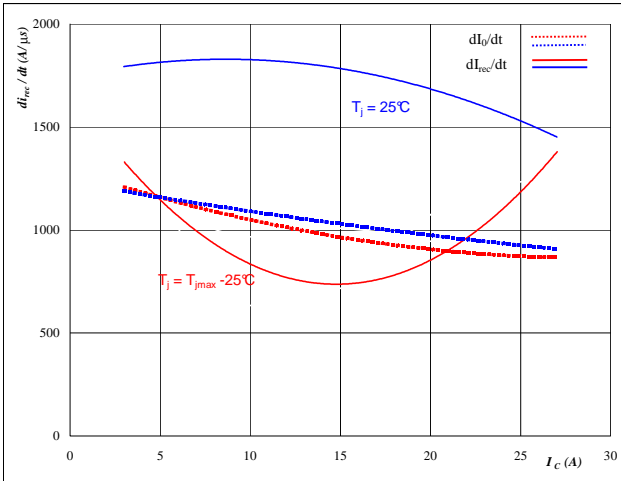
| | | |
|------------|--------|----|
| $T_j =$ | 25/125 | °C |
| $V_R =$ | 400 | V |
| $I_F =$ | 21 | A |
| $V_{GS} =$ | 10 | V |

PFC

Figure 17 PFC FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current

$dI_f/dt, dI_{rec}/dt = f(I_c)$

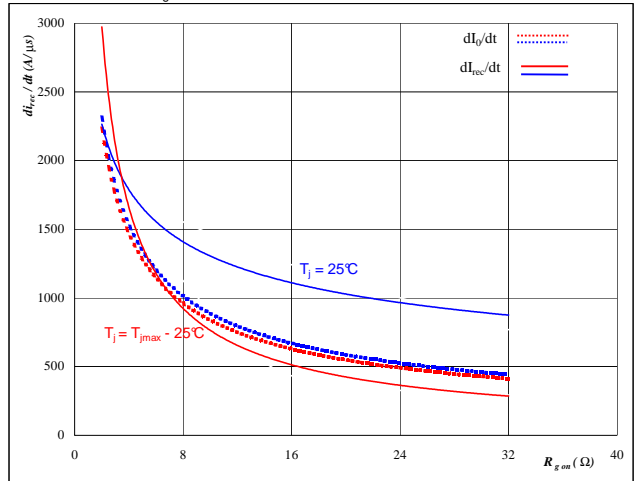


At
 $T_j = 25/125 \text{ } ^\circ\text{C}$
 $V_{CE} = 400 \text{ V}$
 $V_{GE} = 10 \text{ V}$
 $R_{gon} = 8,01 \text{ } \Omega$

Figure 18 PFC FWD

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$dI_f/dt, dI_{rec}/dt = f(R_{gon})$

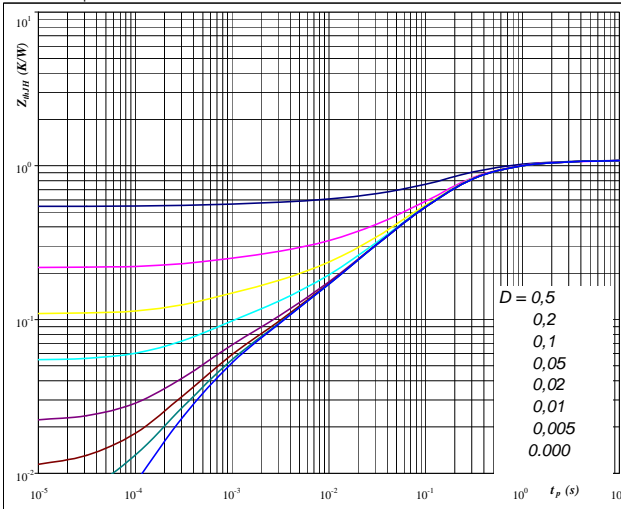


At
 $T_j = 25/125 \text{ } ^\circ\text{C}$
 $V_R = 400 \text{ V}$
 $I_F = 21 \text{ A}$
 $V_{GS} = 10 \text{ V}$

Figure 19 PFC IGBT/MOSFET

IGBT/MOSFET transient thermal impedance as a function of pulse width

$Z_{thJH} = f(t_p)$



At
 $D = t_p / T$
 $R_{thJH} = 1,09 \text{ K/W}$ $R_{thJH} = 0,88 \text{ K/W}$

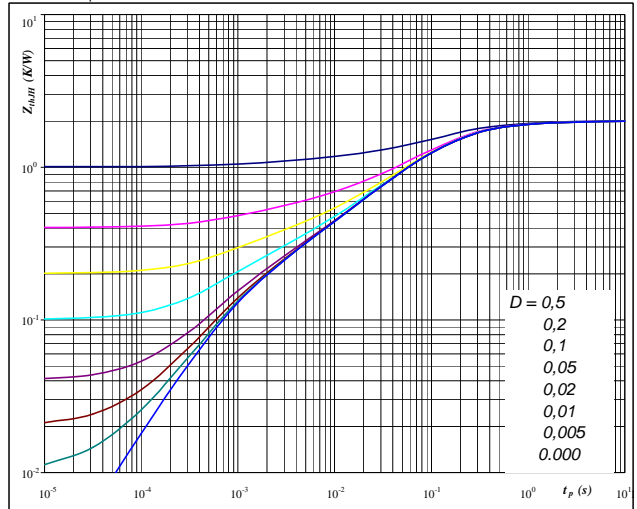
IGBT thermal model values

| Thermal grease | | Phase change interface | |
|----------------|----------|------------------------|----------|
| R (C/W) | Tau (s) | R (C/W) | Tau (s) |
| 0,06 | 3,95E+00 | 0,05 | 3,20E+00 |
| 0,28 | 4,91E-01 | 0,23 | 3,98E-01 |
| 0,53 | 1,37E-01 | 0,43 | 1,11E-01 |
| 0,13 | 2,28E-02 | 0,11 | 1,85E-02 |
| 0,05 | 3,27E-03 | 0,04 | 2,66E-03 |
| 0,03 | 5,12E-04 | 0,03 | 4,15E-04 |

Figure 20 PFC FWD

FWD transient thermal impedance as a function of pulse width

$Z_{thJH} = f(t_p)$



At
 $D = t_p / T$
 $R_{thJH} = 2,02 \text{ K/W}$ $R_{thJH} = 1,63 \text{ K/W}$

FWD thermal model values

| Thermal grease | | Phase change interface | |
|----------------|----------|------------------------|----------|
| R (C/W) | Tau (s) | R (C/W) | Tau (s) |
| 0,06 | 6,73E+00 | 0,05 | 5,46E+00 |
| 0,32 | 5,93E-01 | 0,26 | 4,80E-01 |
| 1,04 | 1,16E-01 | 0,85 | 9,40E-02 |
| 0,33 | 2,53E-02 | 0,26 | 2,05E-02 |
| 0,14 | 5,39E-03 | 0,12 | 4,37E-03 |
| 0,12 | 8,83E-04 | 0,10 | 7,16E-04 |

PFC
Figure 21 PFC IGBT/MOSFET

Power dissipation as a function of heatsink temperature

$$P_{tot} = f(T_h)$$

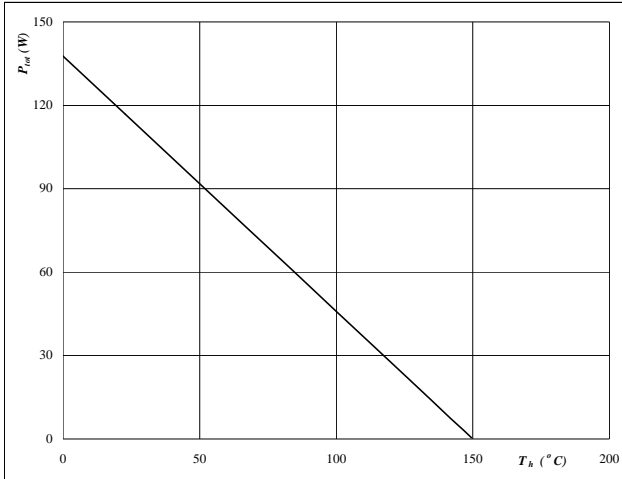

At
 $T_j = 150$ °C

Figure 22 PFC IGBT/MOSFET

Collector/Drain current as a function of heatsink temperature

$$I_C = f(T_h)$$

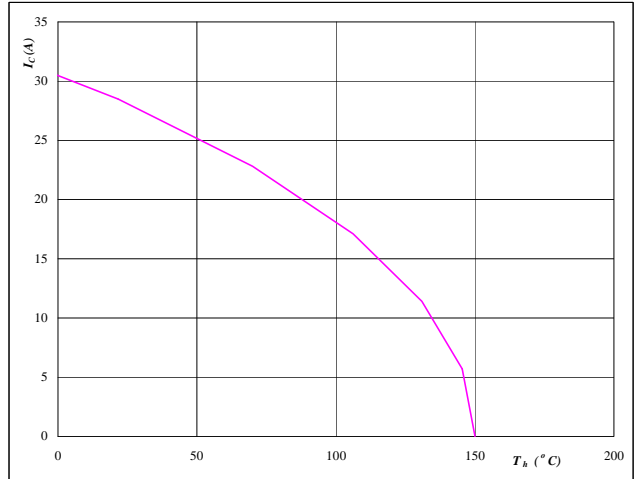

At
 $T_j = 150$ °C
 $V_{GS} = 10$ V

Figure 23 PFC FWD

Power dissipation as a function of heatsink temperature

$$P_{tot} = f(T_h)$$

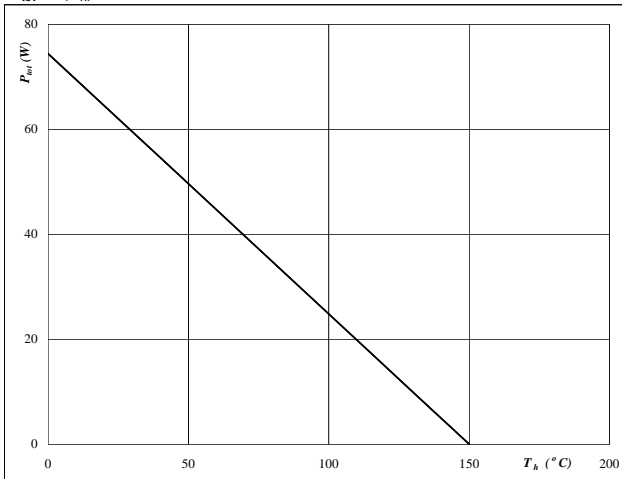
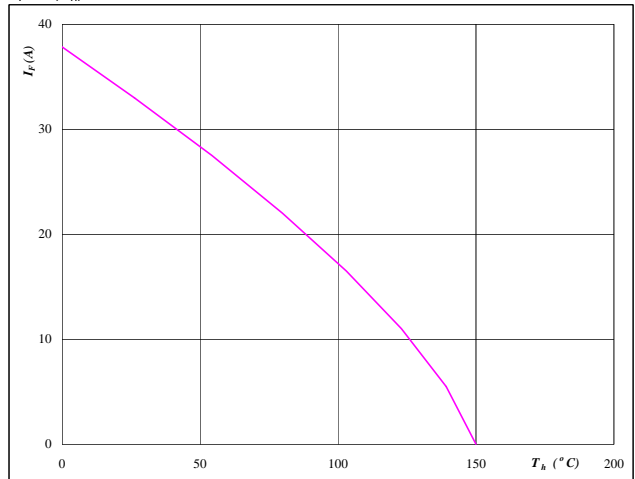

At
 $T_j = 150$ °C

Figure 24 PFC FWD

Forward current as a function of heatsink temperature

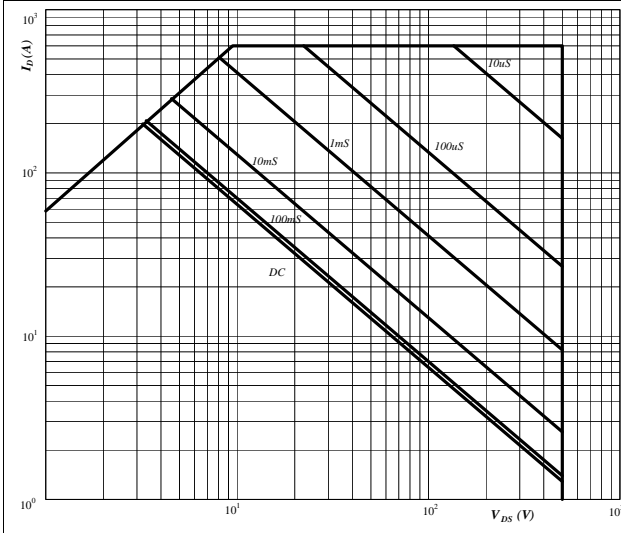
$$I_F = f(T_h)$$


At
 $T_j = 150$ °C

PFC
Figure 25 PFC MOSFET

Safe operating area as a function of drain-source voltage

$$I_D = f(V_{DS})$$

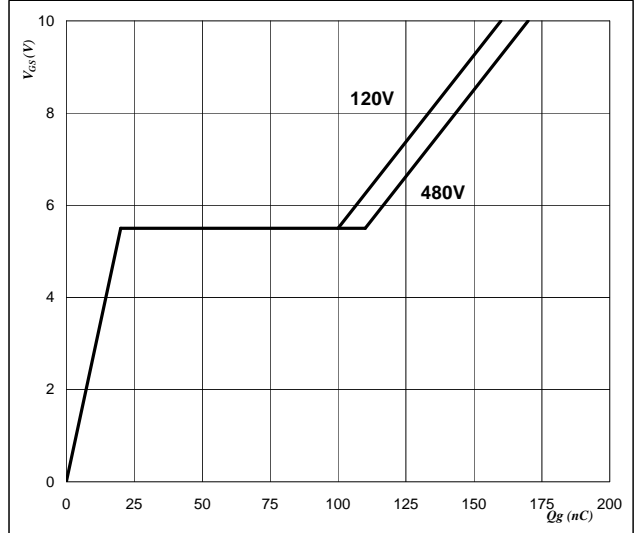


At
 D = single pulse
 $T_h = 80 \text{ } ^\circ\text{C}$
 $V_{GS} = 10 \text{ V}$
 $T_j = T_{jmax} \text{ } ^\circ\text{C}$

Figure 26 PFC MOSFET

Gate voltage vs Gate charge

$$V_{GS} = f(Q_g)$$

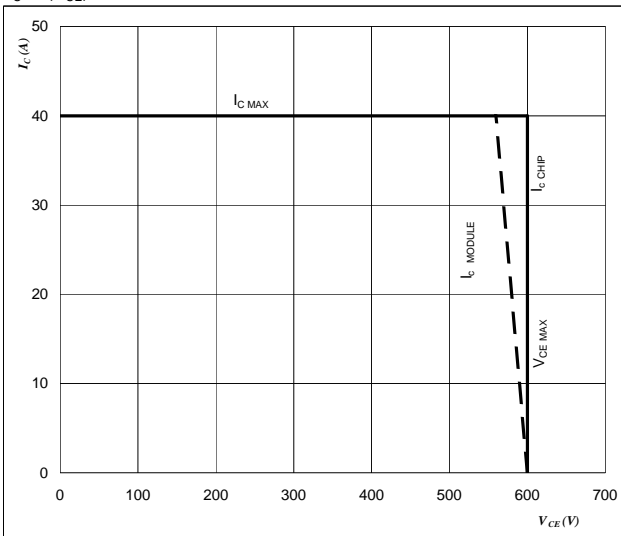


At
 $I_D = 21 \text{ A}$

Figure 29 IGBT

Reverse bias safe operating area

$$I_C = f(V_{CE})$$



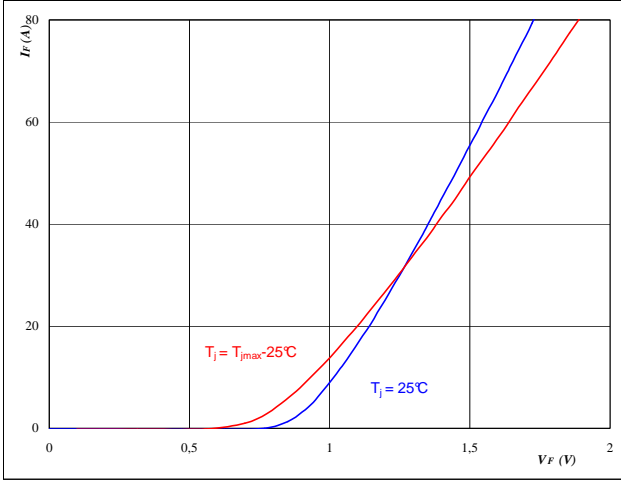
At
 $T_j = T_{jmax} - 25 \text{ } ^\circ\text{C}$
 $U_{ccminus} = U_{ccplus}$
 Switching mode : 3phase SPWM

Input Rectifier Bridge

Figure 1 Rectifier diode

Typical diode forward current as a function of forward voltage

$$I_F = f(V_F)$$

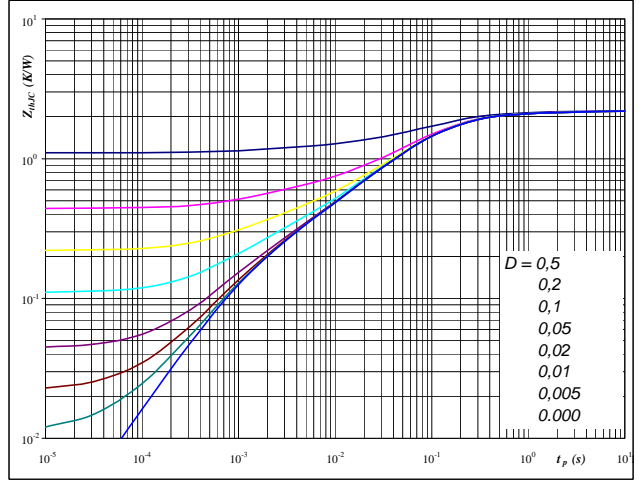


At
 $t_p = 250 \mu s$

Figure 2 Rectifier diode

Diode transient thermal impedance as a function of pulse width

$$Z_{thJH} = f(t_p)$$

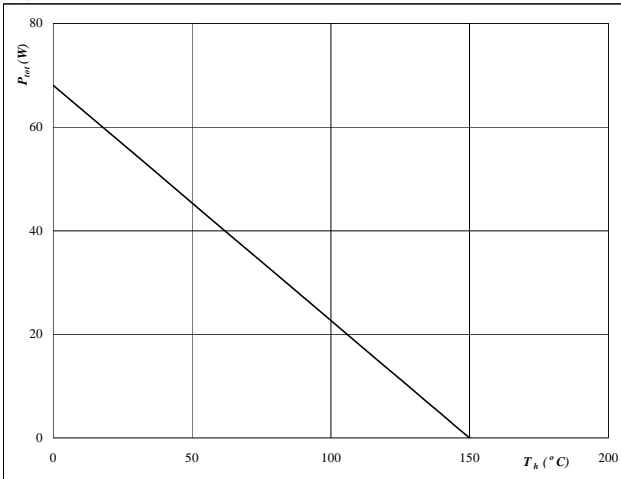


At
 $D = t_p / T$
 $R_{thJH} = 2,20 \text{ K/W}$

Figure 3 Rectifier diode

Power dissipation as a function of heatsink temperature

$$P_{tot} = f(T_h)$$

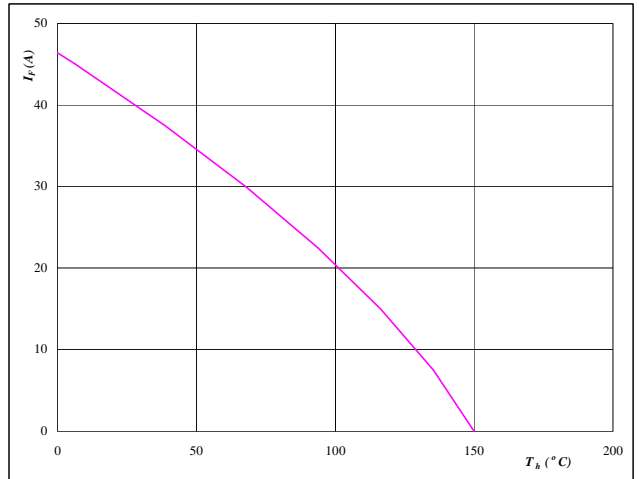


At
 $T_j = 150 \text{ °C}$

Figure 4 Rectifier diode

Forward current as a function of heatsink temperature

$$I_F = f(T_h)$$



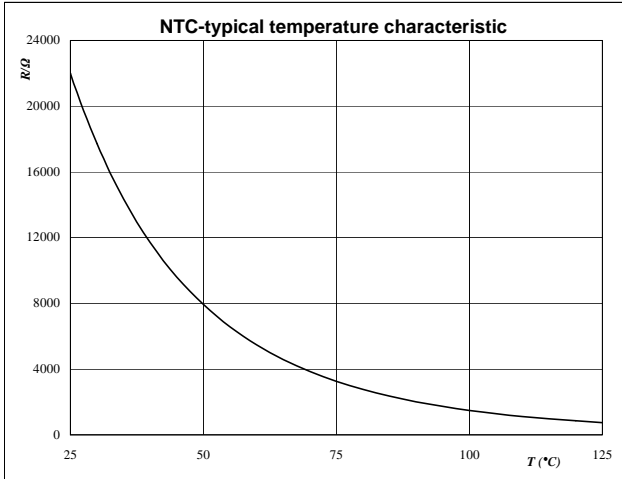
At
 $T_j = 150 \text{ °C}$

Thermistor

Figure 1 Thermistor

Typical NTC characteristic
 as a function of temperature

$$R_T = f(T)$$


Figure 2 Thermistor

Typical NTC resistance values

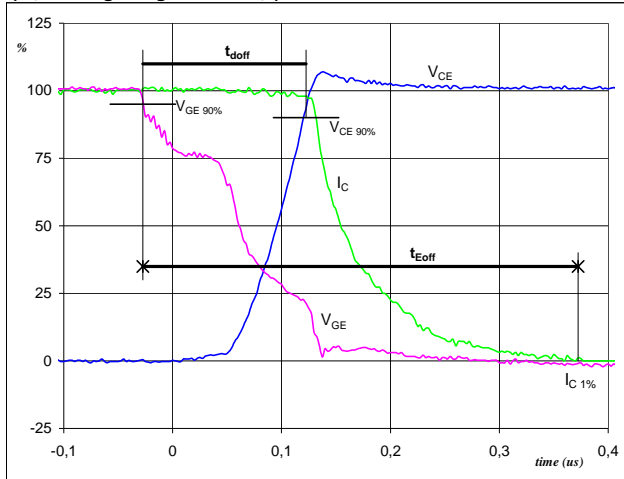
$$R(T) = R_{25} \cdot e^{\left(B_{25/100} \left(\frac{1}{T} - \frac{1}{T_{25}} \right) \right)} \quad [\Omega]$$

| T [°C] | R _{nom} [Ω] | R _{min} [Ω] | R _{max} [Ω] | ΔR/R [±%] |
|------------|-------------------------|-------------------------|-------------------------|--------------|
| -55 | 2089434,5 | 1506495,4 | 2672373,6 | 27,9 |
| 0 | 71804,2 | 59724,4 | 83884 | 16,8 |
| 10 | 43780,4 | 37094,4 | 50466,5 | 15,3 |
| 20 | 27484,6 | 23684,6 | 31284,7 | 13,8 |
| 25 | 22000 | 19109,3 | 24890,7 | 13,1 |
| 30 | 17723,3 | 15512,2 | 19934,4 | 12,5 |
| 60 | 5467,9 | 4980,6 | 5955,1 | 8,9 |
| 70 | 3848,6 | 3546 | 4151,1 | 7,9 |
| 80 | 2757,7 | 2568,2 | 2947,1 | 6,9 |
| 90 | 2008,9 | 1889,7 | 2128,2 | 5,9 |
| 100 | 1486,1 | 1411,8 | 1560,4 | 5 |
| 150 | 400,2 | 364,8 | 435,7 | 8,8 |

Switching Definitions Output Inverter

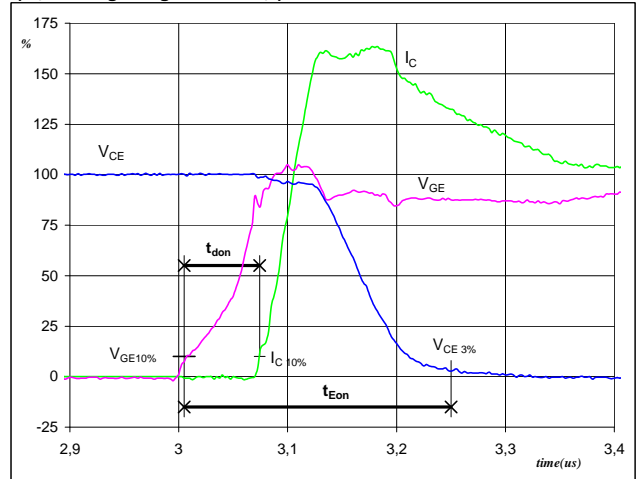
| General conditions | |
|--------------------|---------------|
| T_j | = 125 °C |
| R_{gon} | = 16 Ω |
| R_{goff} | = 16 Ω |

Figure 1 Output inverter IGBT

Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff}
 (t_{Eoff} = integrating time for E_{off})


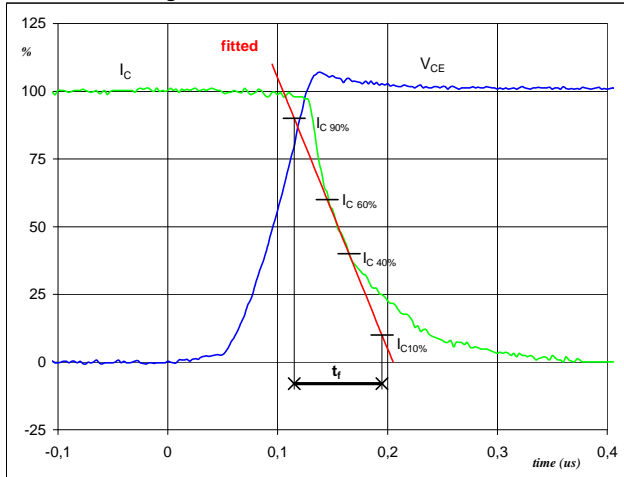
| | | |
|-------------------|------|---------|
| $V_{GE}(0\%) =$ | -15 | V |
| $V_{GE}(100\%) =$ | 15 | V |
| $V_C(100\%) =$ | 400 | V |
| $I_C(100\%) =$ | 21 | A |
| $t_{doff} =$ | 0,15 | μ S |
| $t_{Eoff} =$ | 0,40 | μ S |

Figure 2 Output inverter IGBT

Turn-on Switching Waveforms & definition of t_{don} , t_{Eon}
 (t_{Eon} = integrating time for E_{on})


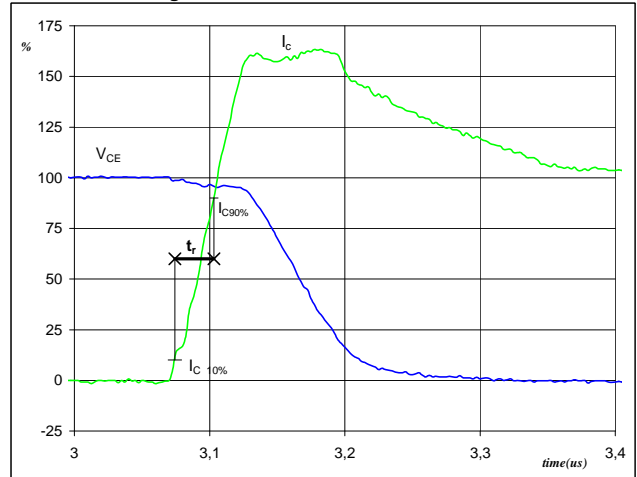
| | | |
|-------------------|------|---------|
| $V_{GE}(0\%) =$ | -15 | V |
| $V_{GE}(100\%) =$ | 15 | V |
| $V_C(100\%) =$ | 400 | V |
| $I_C(100\%) =$ | 21 | A |
| $t_{don} =$ | 0,07 | μ S |
| $t_{Eon} =$ | 0,24 | μ S |

Figure 3 Output inverter IGBT

Turn-off Switching Waveforms & definition of t_f


| | | |
|----------------|------|---------|
| $V_C(100\%) =$ | 400 | V |
| $I_C(100\%) =$ | 21 | A |
| $t_f =$ | 0,08 | μ S |

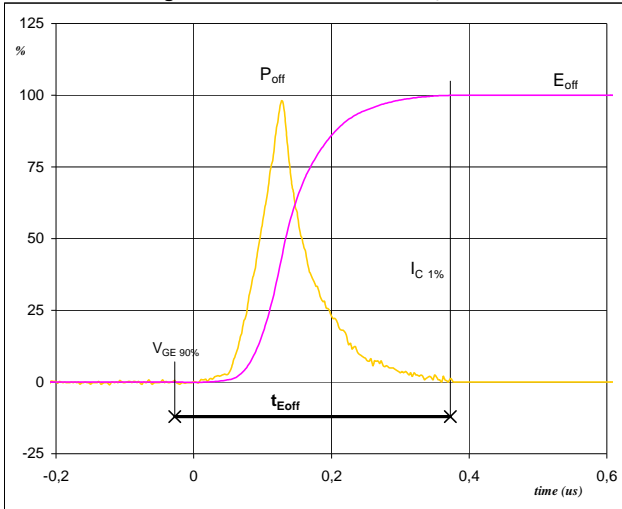
Figure 4 Output inverter IGBT

Turn-on Switching Waveforms & definition of t_r


| | | |
|----------------|------|---------|
| $V_C(100\%) =$ | 400 | V |
| $I_C(100\%) =$ | 21 | A |
| $t_r =$ | 0,03 | μ S |

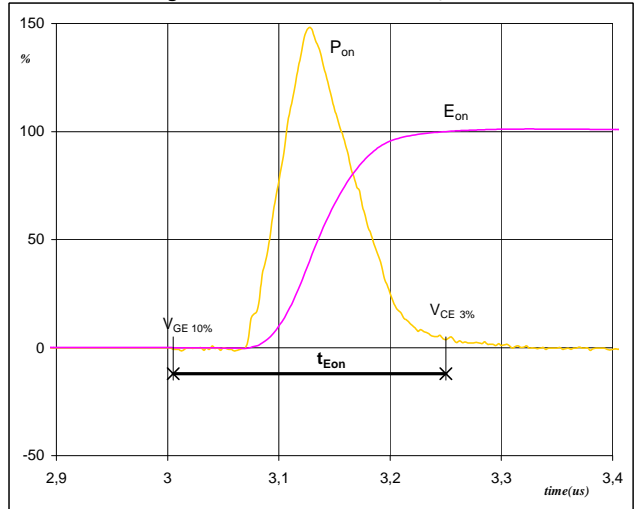
Switching Definitions Output Inverter

Figure 5 Output inverter IGBT

Turn-off Switching Waveforms & definition of t_{Eoff}


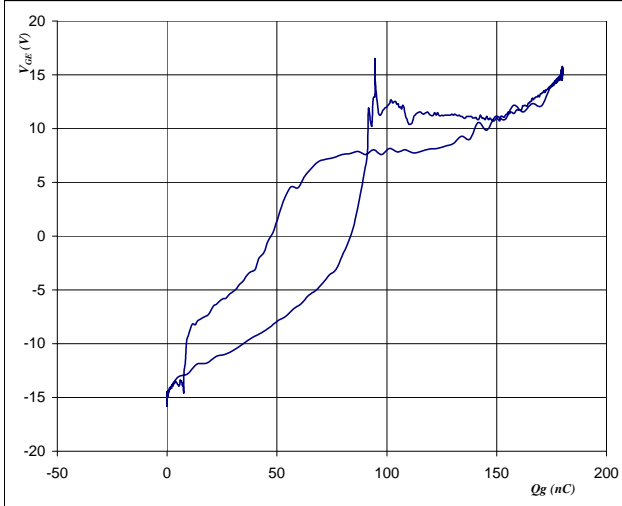
$P_{off} (100\%) = 8,37$ kW
 $E_{off} (100\%) = 0,71$ mJ
 $t_{Eoff} = 0,40$ μ s

Figure 6 Output inverter IGBT

Turn-on Switching Waveforms & definition of t_{Eon}


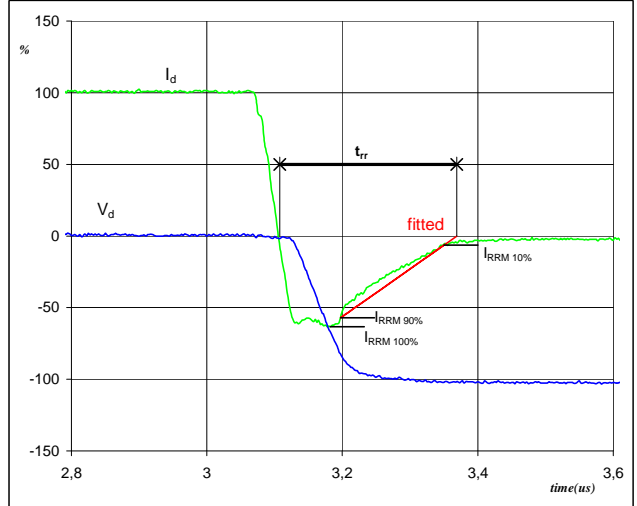
$P_{on} (100\%) = 8,37$ kW
 $E_{on} (100\%) = 0,96$ mJ
 $t_{Eon} = 0,24$ μ s

Figure 7 Output inverter FWD

Gate voltage vs Gate charge (measured)


$V_{GEoff} = -15$ V
 $V_{GEon} = 15$ V
 $V_C (100\%) = 400$ V
 $I_C (100\%) = 21$ A
 $Q_g = 179,93$ nC

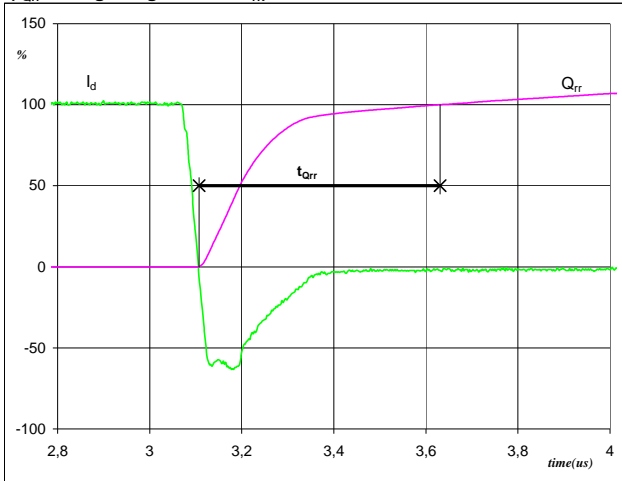
Figure 8 Output inverter IGBT

Turn-off Switching Waveforms & definition of t_{rr}


$V_d (100\%) = 400$ V
 $I_d (100\%) = 21$ A
 $I_{RRM} (100\%) = -13$ A
 $t_{rr} = 0,26$ μ s

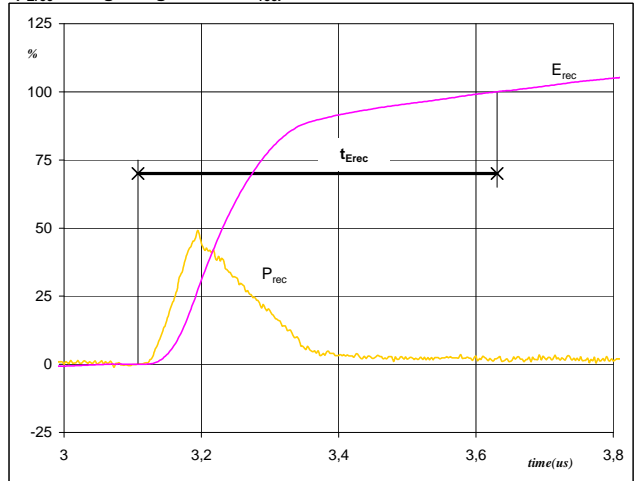
Switching Definitions Output Inverter

Figure 9 Output inverter FWD

Turn-on Switching Waveforms & definition of t_{Qrr}
 (t_{Qrr} = integrating time for Q_{rr})


| | | |
|-------------------|------|---------------|
| I_d (100%) = | 21 | A |
| Q_{rr} (100%) = | 2,01 | μC |
| t_{Qrr} = | 0,52 | μs |

Figure 10 Output inverter FWD

Turn-on Switching Waveforms & definition of t_{Erec}
 (t_{Erec} = integrating time for E_{rec})


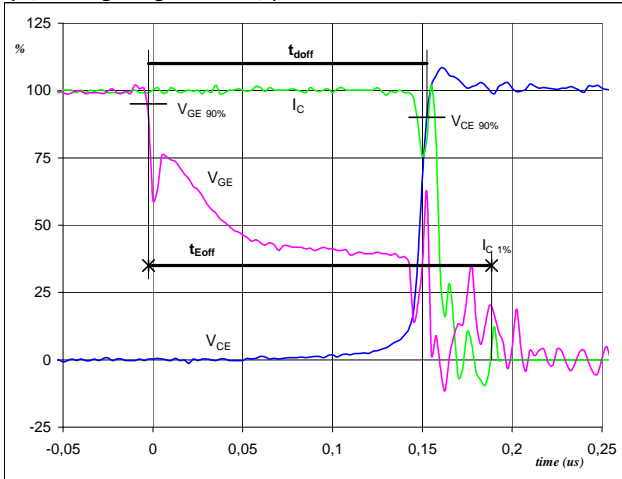
| | | |
|--------------------|------|---------------|
| P_{rec} (100%) = | 8,37 | kW |
| E_{rec} (100%) = | 0,54 | mJ |
| t_{Erec} = | 0,52 | μs |

Switching Definitions PFC

| General conditions | |
|--------------------|----------|
| T_j | = 125 °C |
| R_{gon} | = 8 Ω |
| R_{goff} | = 8 Ω |

Figure 1 PFC MOSFET

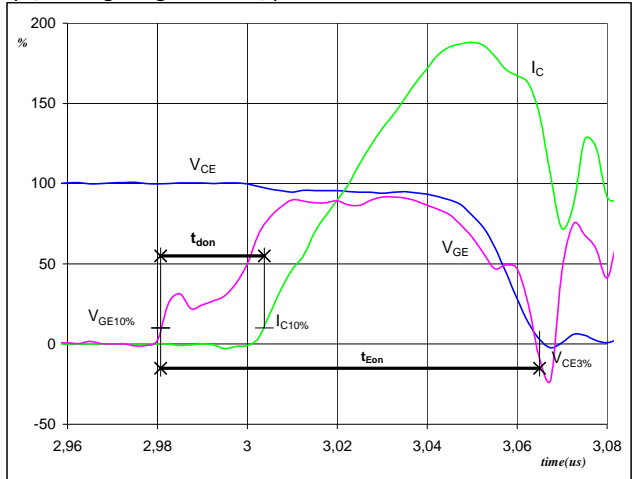
Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff}
(t_{Eoff} = integrating time for E_{off})



| | | |
|-------------------|------|----|
| $V_{GE}(0\%) =$ | 0 | V |
| $V_{GE}(100\%) =$ | 10 | V |
| $V_C(100\%) =$ | 400 | V |
| $I_C(100\%) =$ | 21 | A |
| $t_{doff} =$ | 0,16 | μs |
| $t_{Eoff} =$ | 0,19 | μs |

Figure 2 PFC MOSFET

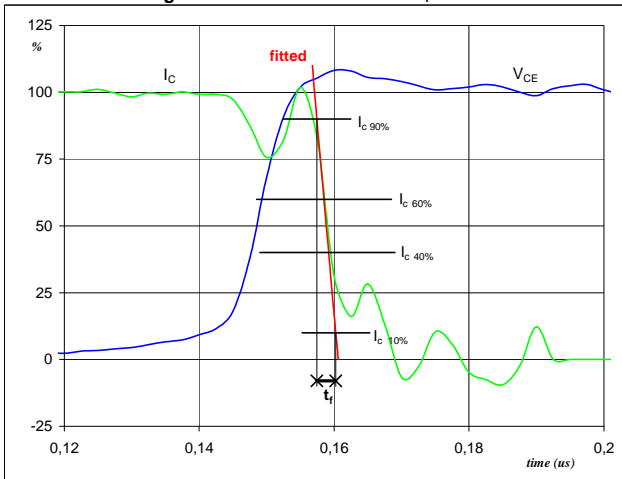
Turn-on Switching Waveforms & definition of t_{don} , t_{Eon}
(t_{Eon} = integrating time for E_{on})



| | | |
|-------------------|------|----|
| $V_{GE}(0\%) =$ | 0 | V |
| $V_{GE}(100\%) =$ | 10 | V |
| $V_C(100\%) =$ | 400 | V |
| $I_C(100\%) =$ | 21 | A |
| $t_{don} =$ | 0,03 | μs |
| $t_{Eon} =$ | 0,08 | μs |

Figure 3 PFC MOSFET

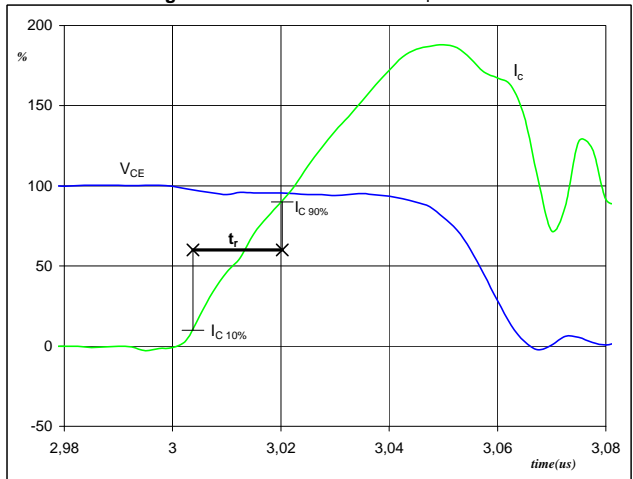
Turn-off Switching Waveforms & definition of t_f



| | | |
|----------------|--------|----|
| $V_C(100\%) =$ | 400 | V |
| $I_C(100\%) =$ | 21 | A |
| $t_f =$ | 0,0040 | μs |

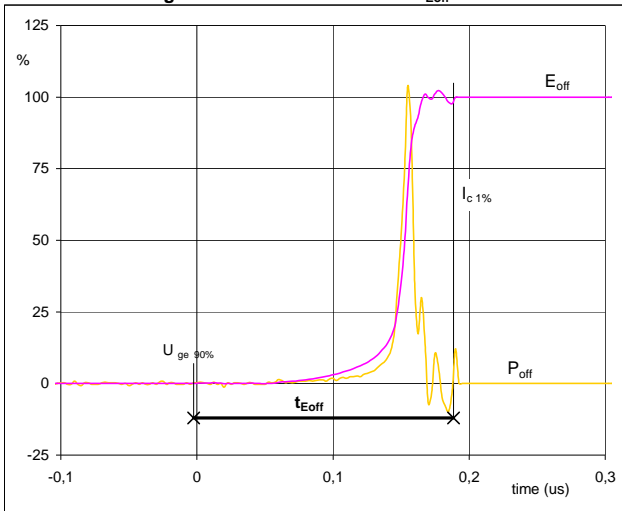
Figure 4 PFC MOSFET

Turn-on Switching Waveforms & definition of t_r

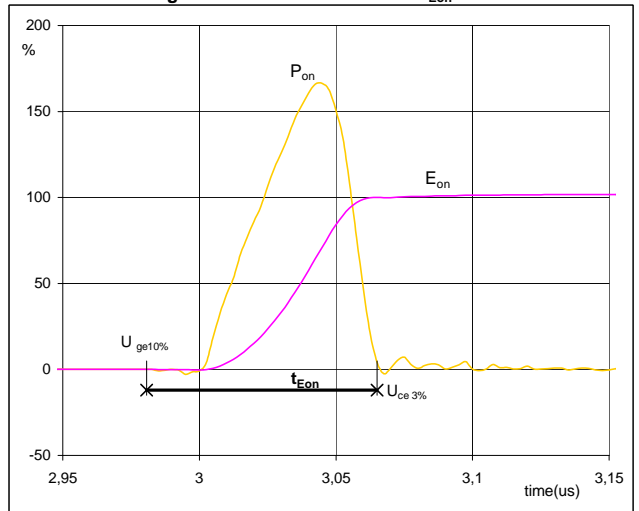


| | | |
|----------------|--------|----|
| $V_C(100\%) =$ | 400 | V |
| $I_C(100\%) =$ | 21 | A |
| $t_r =$ | 0,0160 | μs |

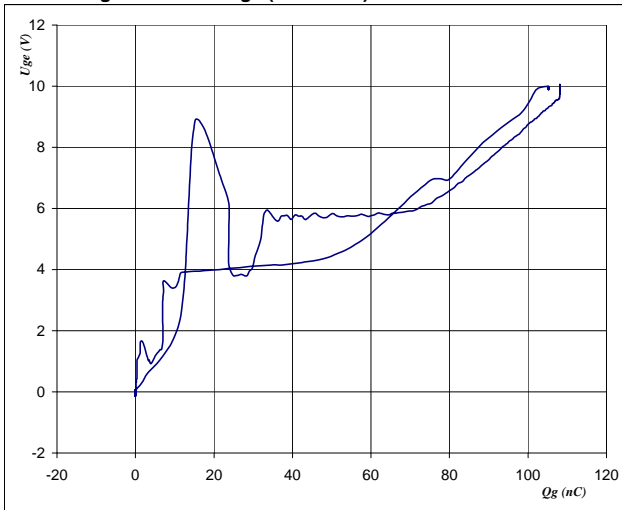
Switching Definitions PFC

Figure 5 PFC MOSFET
Turn-off Switching Waveforms & definition of t_{Eoff}


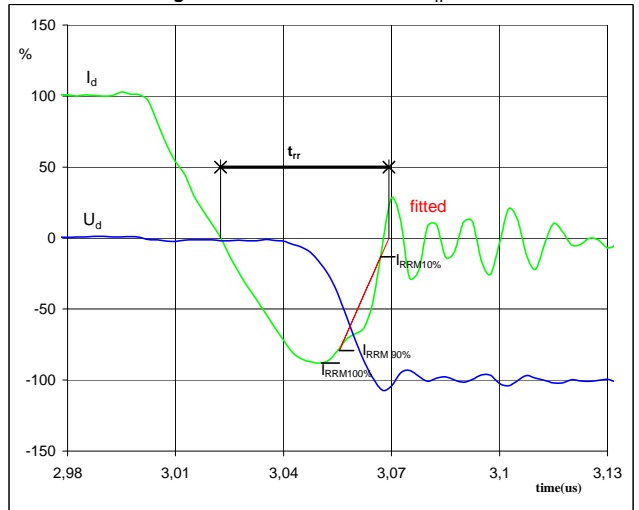
$P_{off} (100\%) = 8,37 \text{ kW}$
 $E_{off} (100\%) = 0,11 \text{ mJ}$
 $t_{Eoff} = 0,19 \text{ } \mu\text{s}$

Figure 6 PFC MOSFET
Turn-on Switching Waveforms & definition of t_{Eon}


$P_{on} (100\%) = 8,3652 \text{ kW}$
 $E_{on} (100\%) = 0,53 \text{ mJ}$
 $t_{Eon} = 0,0843 \text{ } \mu\text{s}$

Figure 7 PFC MOSFET
Gate voltage vs Gate charge (measured)


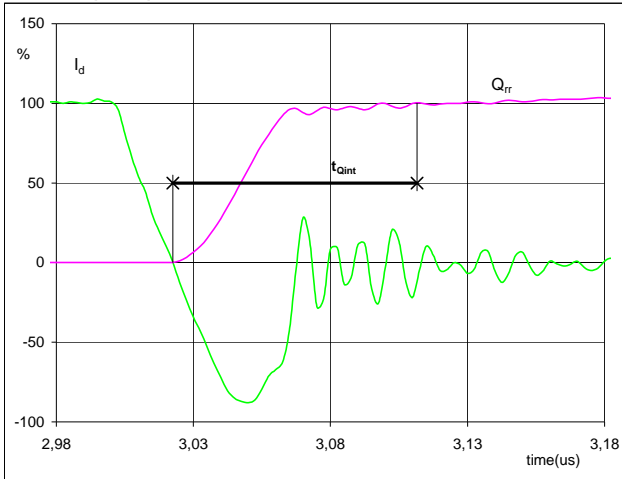
$V_{GEoff} = 0 \text{ V}$
 $V_{GEon} = 10 \text{ V}$
 $V_C (100\%) = 400 \text{ V}$
 $I_C (100\%) = 21 \text{ A}$
 $Q_g = 108,06 \text{ nC}$

Figure 8 PFC FWD
Turn-off Switching Waveforms & definition of t_{rr}


$V_d (100\%) = 400 \text{ V}$
 $I_d (100\%) = 21 \text{ A}$
 $I_{RRM} (100\%) = -18 \text{ A}$
 $t_{rr} = 0,05 \text{ } \mu\text{s}$

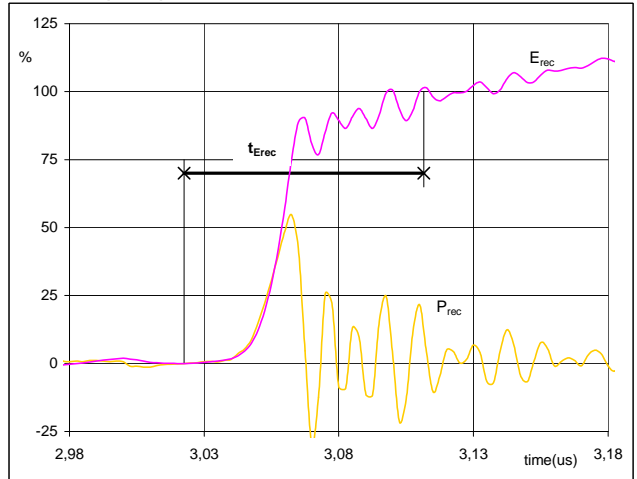
Switching Definitions PFC

Figure 9 PFC FWD

Turn-on Switching Waveforms & definition of t_{Qrr}
 (t_{Qrr} = integrating time for Q_{rr})


| | | |
|-------------------|------|---------------|
| I_d (100%) = | 21 | A |
| Q_{rr} (100%) = | 0,57 | μC |
| t_{Qint} = | 0,09 | μs |

Figure 10 PFC FWD

Turn-on Switching Waveforms & definition of t_{Erec}
 (t_{Erec} = integrating time for E_{rec})


| | | |
|--------------------|------|---------------|
| P_{rec} (100%) = | 8,37 | kW |
| E_{rec} (100%) = | 0,08 | mJ |
| t_{Erec} = | 0,09 | μs |

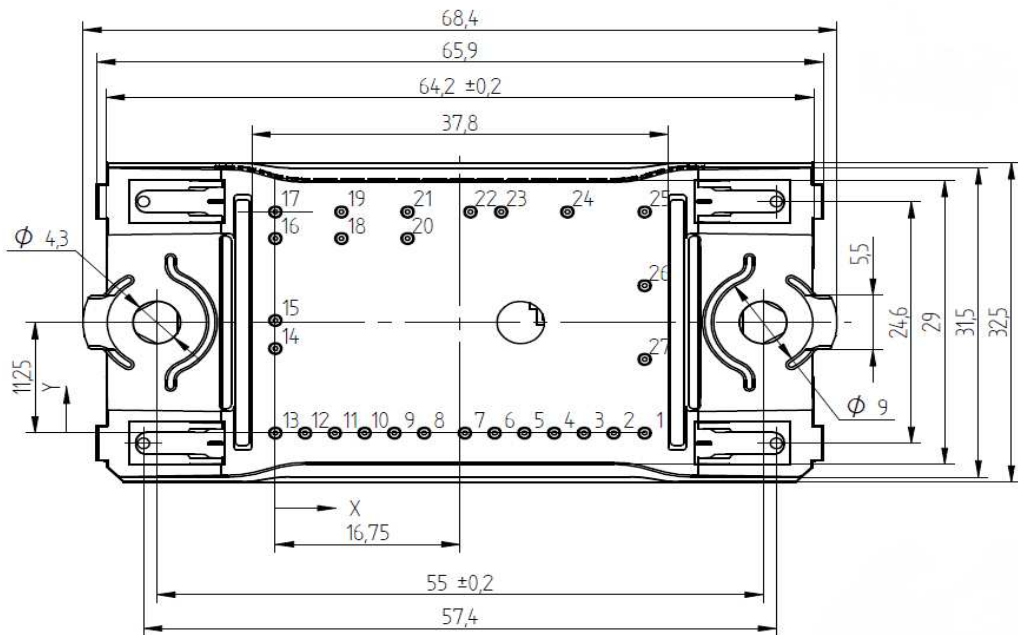
Ordering Code and Marking - Outline - Pinout

Ordering Code & Marking

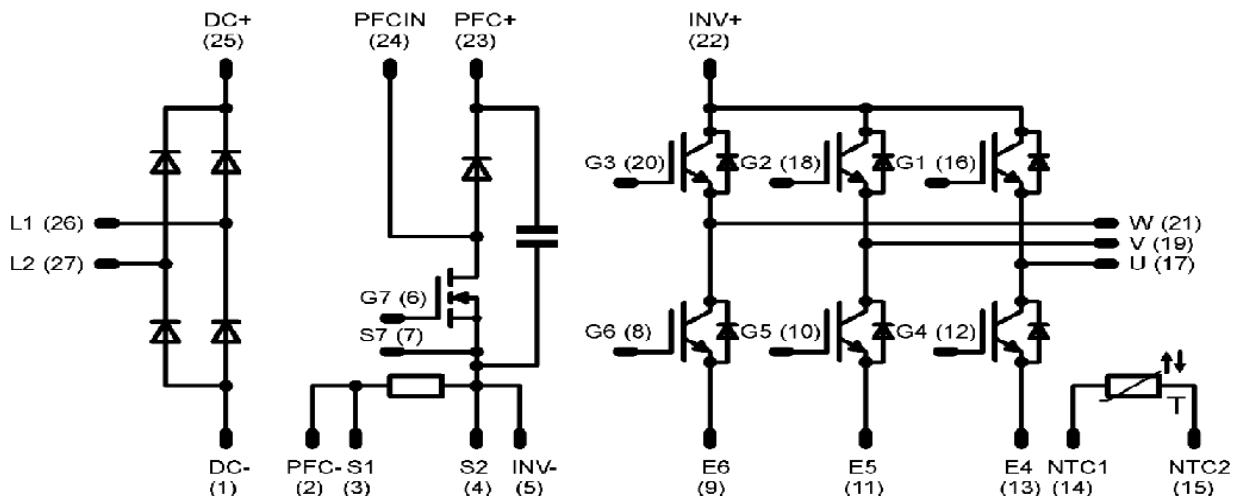
| Version | Ordering Code | in DataMatrix as | in packaging barcode as |
|------------------------------------|-----------------------|------------------|-------------------------|
| without thermal paste 17mm housing | 10-F006PPA020SB-M685B | M685B | M685B |

Outline

| Pin table | | |
|-----------|-----|-----|
| Pin | X | Y |
| 1 | 335 | 0 |
| 2 | 307 | 0 |
| 3 | 28 | 0 |
| 4 | 253 | 0 |
| 5 | 226 | 0 |
| 6 | 199 | 0 |
| 7 | 172 | 0 |
| 8 | 145 | 0 |
| 9 | 118 | 0 |
| 10 | 91 | 0 |
| 11 | 64 | 0 |
| 12 | 37 | 0 |
| 13 | 0 | 86 |
| 14 | 0 | 114 |
| 15 | 0 | 142 |
| 16 | 0 | 170 |
| 17 | 0 | 198 |
| 18 | 6 | 225 |
| 19 | 6 | 253 |
| 20 | 12 | 280 |
| 21 | 12 | 308 |
| 22 | 17 | 335 |
| 23 | 20 | 363 |
| 24 | 26 | 390 |
| 25 | 33 | 417 |
| 26 | 33 | 445 |
| 27 | 33 | 473 |



Pinout



PRODUCT STATUS DEFINITIONS

| Datasheet Status | Product Status | Definition |
|-------------------------|------------------------|--|
| Target | Formative or In Design | This datasheet contains the design specifications for product development. Specifications may change in any manner without notice. The data contained is exclusively intended for technically trained staff. |
| Preliminary | First Production | This datasheet contains preliminary data, and supplementary data may be published at a later date. Vincotech reserves the right to make changes at any time without notice in order to improve design. The data contained is exclusively intended for technically trained staff. |
| Final | Full Production | This datasheet contains final specifications. Vincotech reserves the right to make changes at any time without notice in order to improve design. The data contained is exclusively intended for technically trained staff. |

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.